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S SERIES DC/DC MODULES

Applications Networking Gear

- · Servers, Switches and Data Storage
- Wireless Communications
- · Distributed Power Architecture
- Data Communications Telecommunications
- Industrial / Medical

Semiconductor Test Equipment

The S Families of high efficiency non-isolated DC/DC converters offer power levels of up to 80 Watt, which exceeds that of other Industry-standard SMT and Through-Hole SIPs with the same package, while also providing ultra-wide input voltage range for 3.3Vin and 5Vin. These converters provide versatility without sacrificing the board space. All models feature an input filter and regulated outputs. The open-frame construction facilitates maximum power delivered with the highest efficiency of up to 95%. All converters combine creative design practices with highly derated power devices to achieve very high reliability, high performance and low cost solution to systems designers. INPUT SPECIFICATIONS

Specifications & Features Summary

- Industry Standard SIP or SMT Pinout
- High Efficiency to 95%
- Ultra-Wide Input Voltage Range
- User-Adjustable Outputs (S10-12S5, S15 & S16 Models)
- Over Temperature Protection
- Continuous Short Circuit Protection

SMT PACKAGE S10, S15 & S16 SERIES

- 33.0

- Remote ON/OFF
- Pending UL Approval
- PLEASE ADD SUFFIX "T" FOR THROUGH-HOLE PACKAGE
- PLEASE ADD SUFFIX "N" FOR NEGATIVE LOGIC CONTROL⁵

MODEL	INPUT	OUTPUT	OUTPUT	INPUT (CURRENT	%	
NUMBER	VOLTAGE	VOLTAGE	CURRENT	NO LOAD	FULL LOAD	EFF	PACKAGE
S10-5S1.0	3.0 -5.5VDC	1.0 Vdc	10 A	50 mA	2353mA	85	SIP / SMT
S10-5S1.2	3.0 -5.5VDC	1.2 Vdc	10 A	50 mA	2791mA	86	SIP / SMT
S10-5S1.5	3.0 -5.5VDC	1.5 Vdc	10 A	50 mA	3409mA	88	SIP / SMT
S10-5S1.8	3.0 -5.5VDC	1.8 Vdc	10 A	50 mA	4000mA	90	SIP / SMT
S10-5S2.0	3.0 -5.5VDC	2.0 Vdc	10 A	60 mA	4396mA	91	SIP / SMT
S10-5S2.5	3.0 -5.5VDC	2.5 Vdc	10 A	60 mA	5376mA	93	SIP / SMT
S10-5S3.3	4.5 –5.5VDC	3.3 Vdc	10 A	60 mA	6947mA	95	SIP / SMT
S10-12S5	8.3 -14.0VDC	0.75-5Vdc	10 A	Various	Various	93 max.	SIP / SMT
S15-5S3.3	3.0 -5.5VDC	0.9-3.63 Vdc	15 A	Various	Various	94 max.	SIP / SMT
S16-12S5	9.0 -14.0VDC	0.75-5Vdc	16A	Various	Various	94 max.	SIP / SMT

Typical at Ta= +25 °C under nominal input voltages of 5V and 12VDC, unless noted. The information and specifications contained in this brief are believed to be accurate and reliable at the time of publication. Specifications are subject to change without notice. Refer to product specification sheet for performance characteristics and application guidelines.

Consult factory for hundreds of other available input/output voltage

9.30

(0.366)

	IN OT OF EOIL	OATIONS				
	Under Voltage Lockout Power-Up/Power-Down (S	S10 & S15)	2.8V typ. / 2.7V typ.			
	S10-12S5		8.0V typ. / 7.7V typ.			
	S16-12S5	8.5V typ. / 8.0V typ.				
	Input Filter Type		Capacitive			
	Positive Remote on/off Control: Module ON		Open Circuit or Vin High			
	Module OFF		<0.4Vdc			
	OUTPUT SPECI	FICATIONS				
	Voltage Accuracy		±1.5% max.			
	Transient Response: 25% Step Load Change		<200u sec.			
	Ripple and Noise, 20MHz BW, Note 3					
	\$10 / \$15 - 20mV rms max. (50mV pk-pk max).		ms max.(75mV pk-pk max)			
	Temperature Coefficient		±0.03%/C max.			
d	Short Circuit Protection		Continuous			
ı	Line Regulation, Note1	±0.2% max	., (SMT S15 is ±0.4% max)			
ı	Load Regulation, Note2		±0.5% max.			
ı	External Trim Adj. Range (S10 Family)		±10%			
	Efficiency		See Table			
	Isolation Voltage		Not Isolated			
-	Switching Frequency		300KHz typ.			
	Over Temperature Protection	120°C	C typ., 130°C for S16			
	Operating Ambient Temperature Range		-40°C to +85°C			
	Derating Temperature	See	Application Notes			
-	Storage Temperature Range	-	55°C to +125°C			
	Dimensions: (Through-Hole Package) S10/S15	2"x0.5"x0	.33" (50.8x12.7x8.3 mm)			
-	(Through-Hole Package) S10-12S5 & S16	2"x0.512"x0	0.327" (50.8x13.0x8.3 mm)			

Measured from High Line to Low Line	S15(S16) Family Vo, set =1.8(3.3)Vdc
2. Measured from Full Load to Zero Load	S15/16 Family Vo, set =3.3Vdc
Measured with 10uf tantalum cap & 1uf cerami	c cap across output.

1.3"x0.53"x0.366" (33.00x13.46x9.3 mm)

Non-potted With Open Frame Type

S15-5S3.3

External Resistor Values

(SMT Package)

Structure

Recommended Pad Lavout

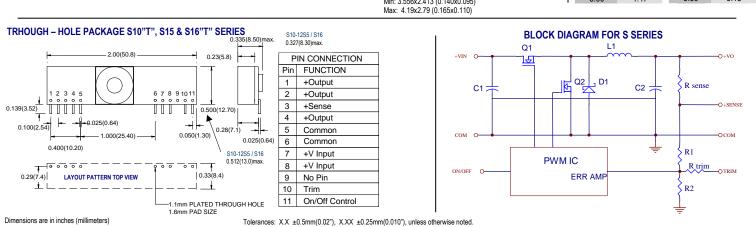
Dimensions are in millimeters (inches)

4. 100uf, ESR <20m Ω (S10/S15) or <100m Ω (S10-12S5/S16)Cap across Vin recommended 5. Suffix "N" to the Model Number with Negative Module ON – Open Circuit or <0.4Vdc

\$10-12\$5 & \$16-12\$5

External Resistor Values

	7.87 4.83 4.83 4.83 7.54	1.65 —	max.	_	7.54 4.83 4.83 7.87		for programming	output voltage	for programming	ig output voltage
	(0.310) (0.190)(0.190) (0.190) (0.297)	(0.065)			(0.297) (0.190)(0.190) (0.190) (0.310)	_	Vo,set	Rtrim	Vo,set	Rtrim
				1		1	(V)	(ΚΩ)	(V)	(ΚΩ)
	COM +VO TRIM +SENSE	,		Ţ	+SENSE TRIM +VO COM	1	0.75	Open	0.90	135.36
		10.29 13.46 (0.405) (0.530)	H	10.29	J ,	10.92	1.20	22.33	1.00	79.17
	BOTTOM VIEW	1	H	(0.405)	TOP VIEW	(0.430)	1.50	13.0	1.20	41.71
	- L +VIN ON/OFF	l <u> </u>		<u>• • </u>	ON/OFF +VIN	,	1.80	9.0	1.50	22.98
1.60 (0.063)		1 - - 	\sqcup	+ :		—— را	2.00	7.4	1.80	14.96
-	SURFACE MOUNT CONTACT	1.01()	J	0.64 (0.025)	29.90		2.50	5.0	2.00	11.75
	2.84 1.2 (0.112) (0.0				PAD SIZE: (1.177)		3.30	3.12	2.50	6.93
	(5.0	/	L1 INDUCT	UK	Min: 3.556x2.413 (0.140x0.095)	l	5.00	1.47	3.30	3.15





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S5 SERIES SIP or SMT Version Application Notes

Applications

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- Wireless Communications
 Distributed Power Architecture
 Semiconductor Test Equipment
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- Data CommunicationsTelecommunications
 - Industrial / Medical

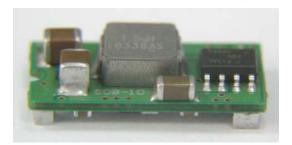
NON-ISOLATED DC-DC Converter

S5-5S3.3T, S5-5S3.3 3.0-5.5Vin, 0.75- 3.63Vout, 5A

APPLICATION NOTE Ver10



S5-5S3.3T (Suffix "T" Indicates Through-Hole Version)



S5-5S3.3



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S5 SERIES SIP or SMT Version Application Notes

Applications

Servers, Switches and Data StorageWireless CommunicationsNetData

Wireless Communications Distributed Power Architecture Semiconductor Test Equipment

Networking GearData CommunicationsTelecommunicationsIndustrial / Medical

Content

1. INTRODUCTION 2. MODELS	3
	3
3. 5A SIP/SMT CONVERTER FEATURES 4. GENERAL DESCRIPTION	3
4.1 Electrical Description	3 3
4.2 Thermal Packaging and Physical Design.	4
	·
5. MAIN FEATURES AND FUNCTIONS5.1 Operating Temperature Range	4 4
5.2 Over-Temperature Protection (OTP)	4
5.3 Output Voltage Adjustment	4
5.4 Safe Operating Area (SOA)	4
5.5 Over Current Protection	4
5.6 Remote ON/OFF	4
5.7 UVLO (Under-Voltage Lockout)	5
6. SAFETY	5
6.1 Input Fusing and Safety Considerations.	5
7. APPLICATIONS	5
7.1 Layout Design Challenges.	5
7.2 Convection Requirements for Cooling	6
7.3 Thermal Considerations	6
7.4 Power De-Rating Curves	7
7.5 Efficiency vs Load Curves	11
7.6 Input Capacitance at the Power Module	13
7.7 Test Set-Up	13
7.8 S5 Series Output Voltage Adustment.	14
7.9 Output Ripple and Noise Measurement	14
7.10 Output Capacitance	14
7.11 SMT Reflow Profile	14
8. MECHANICAL OUTLINE DIAGRAMS	15
8.1 SIP/SMT05 Mechanical Outline Diagrams	15
8.2 SMT Tape and Reel Dimensions	15



S5 SERIES SIP or SMT **Version Application Notes** **Applications**

- · Servers, Switches and Data Storage · Networking Gear
- Wireless Communications
- · Distributed Power Architecture Semiconductor Test Equipment
- Data Communications Telecommunications
- · Industrial / Medical

1. Introduction

This application note describes the features and functions of Intronics' S5 series of Non Isolated DC-DC Converters. These are highly efficient, reliable and compact, high power density, single output DC/DC converters. These "Point of Load" modules serve the needs specifically of the fixed and mobile telecommunications and computing market, employing economical distributed Power Architectures. The S5 series provide precisely regulated output voltage range from 0.75V to 3.63Vdc over a wide range of input voltage (Vi=3.0 - 5.5Vdc) and can operate over an ambient temperature range of -40°C to +85°C. Ultra-high efficiency operation is achieved through the use of synchronous rectification and drive control techniques.

The modules are fully protected against short circuit and overtemperature conditions. Intronics' world class automated manufacturing methods, together with an extensive testing and qualification program, ensure that all S5 series converters are extremely reliable.

2. Models

The adjustable S5 series models are shown in table1.

Model	Input Voltage	Output Voltage	Output Current
S5-5S3.3T	3.0 - 5.5VDC	0.75 - 3.63VDC	5A
S5-5S3.3	3.0 – 5.5VDC	0.75 - 3.63VDC	5A

Table 1 - S5 Series Models

The S5 SERIES efficiency and input current at 5.0Vin are shown in table2.

Output	Output	Input Curi	Input Current (mA)	
Voltage	Current	No Load	Full Load	typ.
0.75V	5A	25	0.949	79%
1.2V	5A	30	1.412	85%
1.5V	5A	30	1.724	87%
1.8V	5A	35	2.022	89%
2.0V	5A	35	2.222	90%
2.5V	5A	35	2.217	92%
3.3V	5A	35	3.511	94%

Table 2 – S5 Series Efficiency and Input Current

3. 5A SIP/SMT Converter Features

- High efficiency topology, typically 94% at 3.3Vdc
- Industry standard footprint
- Wide ambient temperature range, -40C to +85C
- Cost efficient open frame design
- Programmable output voltage via external resistor from 0.75 to 3.63Vdc
- No minimum load requirement (Stable at all loads)
- Remote ON/OFF
- Remote sense compensation
- Fixed switching frequency
- Continuous short-circuit protection and over current protection
- Over-temperature protection (OTP)
- Monotonic Startup with pre-bias at the output.
- UL/IEC/EN60950 Certified.

4. General Description

4.1 Electrical Description

A block diagram of the S5 Series converter is shown in Figure 1. Extremely high efficiency power conversion is achieved through the use of synchronous rectification and drive techniques. Essentially, the powerful S5 series topology is based on a non-isolated synchronous buck converter. The control loop is optimized for unconditional stability, fast transient response and a very tight line and load regulation. In a typical pre-bias application the S5 series converters do not draw any reverse current at start-up. The output voltage can be adjusted from 0.75 to 3.63vdc, using the TRIM pin with a external resistor. The converter can be shut down via a remote ON/OFF input that is referenced to ground. This input is compatible with popular logic devices; a 'positive' logic input is supplied as standard. Positive logic implies that the converter is enabled if the remote ON/OFF input is high (or floating), and disabled if it is low. The converter is also protected against over-temperature conditions. If the converter is overloaded or the ambient temperature gets too high, the converter will shut down to protect the unit.

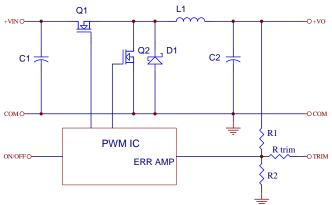


Figure 1. Electrical Block Diagram



S5 SERIES SIP or SMT Version Application Notes

Applications

- Servers, Switches and Data StorageWireless Communications
- Distributed Power Architecture
- Semiconductor Test Equipment
- Networking GearData Communications
- Telecommunications
- Industrial / Medical

4.2 Thermal Packaging and Physical Design.

The S5 series uses a multi-layer FR4 PCB construction. All surface mount power components are placed on one side of the PCB, and all low-power control components are placed on the other side. Thus, the Heat dissipation of the power components is optimized, ensuring that control components are not thermally stressed. The converter is an open-frame product and has no case or case pin. The open-frame design has several advantages over encapsulated closed devices. Among these advantages are:

- Efficient Thermal Management: the heat is removed from the heat generating components without heating more sensitive, small signal control components.
- Environmental: Lead free open-frame converters are more easily re-cycled.
- Cost Efficient: No encapsulation. Cost efficient open-frame construction.
- Reliable: Efficient cooling provided by open frame construction offers high reliability and easy diagnostics.

5. Main Features and Functions

5.1 Operating Temperature Range

Intronics' S5 series converters highly efficient converter design has resulted in its ability to operate over a wide ambient temperature environment (-40°C to 85°C). Due consideration must be given to the de-rating curves when ascertaining maximum power that can be drawn from the converter. The maximum power drawn is influenced by a number of factors, such as:

- Input voltage range.
- Output load current.
- · Air velocity (forced or natural convection).
- Mounting orientation of converter PCB with respect to the Airflow.
- Motherboard PCB design, especially ground and power planes.
 These can be effective heat sinks for the converter.

5.2 Over-Temperature Protection (OTP)

The S5 Series converters are equipped with non-latching overtemperature protection. A temperature sensor monitors the temperature of the hot spot (typically, top switch). If the temperature exceeds a threshold of 120°C (typical) the converter will shut down, disabling the output. When the temperature has decreased the converter will automatically restart.

The over-temperature condition can be induced by a variety of reasons such as external overload condition or a system fan failure.

5.3 Output Voltage Adjustment

Section 7.8 describes in detail as to how to trim the output voltage with respect to its set point. The output voltage on all models is trimmable in the range 0.75-3.63Vdc.

5.4 Safe Operating Area (SOA)

Figure 2 provides a graphical representation of the Safe Operating Area (SOA) of the converter. This representation assumes ambient operating conditions such as airflow are met as per thermal guidelines provided in Sections 7.2 and 7.3.

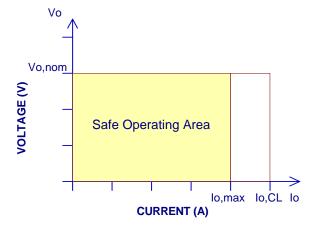


Figure 2. Maximum Output Current Safe Operating Area

5.5 Over Current Protection

All different voltage models have a full continuous short-circuit protection. The unit will auto recover once the short circuit is removed. To provide protection in a fault condition, the unit is equipped with internal over-current protection. The unit operates normally once the fault condition is removed. The power module will supply up to 150% of rated current. In the event of an over current converter will go into a hiccup mode protection.

5.6 Remote ON/OFF

The remote ON/OFF input feature of the converter allows external circuitry to turn the converter ON or OFF. Active-high remote ON/OFF is available as standard. The S5 series converters are turned on if the remote ON/OFF pin is high, or left open or floating. Setting the pin low will turn the converter 'Off'. The signal level of the remote on/off input is defined with respect to ground. If not using the remote on/off pin, leave the pin open (module will be on). The part number suffix "N" is Negative remote ON/OFF version. The unit is guaranteed OFF over the full temperature range if this voltage level exceeds 2.8Vdc. The converters are turned on If the on/off pin input is low or left open. The recommended SIP/SMT remote on/off drive circuit as shown as figure 3, 4.



S5 SERIES SIP or SMT **Version Application Notes** **Applications** · Networking Gear

- · Servers, Switches and Data Storage
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- · Distributed Power Architecture Telecommunications Semiconductor Test Equipment
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 - · Industrial / Medical

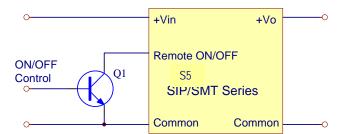


Figure 3. Positive Remote ON/OFF Input Drive Circuit

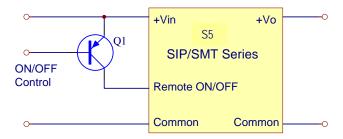


Figure 4. Negative Remote ON/OFF Input Drive Circuit

5.7 UVLO (Under-Voltage Lockout)

The voltage on the Vcc pin determines the start of the operation of the Converter. When the input Vcc rises and exceeds about 2.0V the converter initiates a soft start. The UVLO function in the converter has a hysteresis (about 100mV) built in to provide noise immunity at start-up.

6. Safety

6.1 Input Fusing and Safety Considerations.

Agency Approvals: The power Supply shall be submitted to and receive formal approval from the following test agencies.

- 1. The power supply shall be approved by a nationally recognized testing laboratory to UL/CSA 60950 3rd Edition (North America) and EN60950 (International)
- 2. CB Certificate from an internationally recognized test house in accordance with EN 60950.

The S5 series converters do not have an internal fuse. However, to achieve maximum safety and system protection, always use an input line fuse. The safety agencies require a time-delay fuse with a maximum rating of 10A.

7. Applications

7.1 Layout Design Challenges.

In optimizing thermal design the PCB is utilized as a heat sink. Also some heat is transferred from the SIP/SMT module to the main board through connecting pins. The system designer or the end user must ensure that other components and metal in the vicinity of the S5 series meet the spacing requirements to which the system is approved.

Low resistance and low inductance PCB layout traces are the norm and should be used where possible. Due consideration must also be given to proper low impedance tracks between power module, input and output grounds. The recommended SIP/SMT footprint as shown as figure 5, 6.

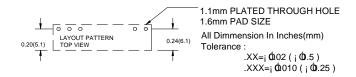


Figure 5. Recommended SIP Footprint

Recommended Pad Layout

Dimensions are in Inches (millimetes)

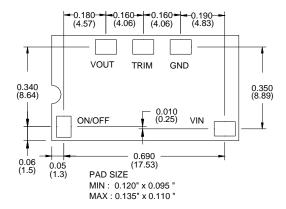


Figure 6. Recommended SMT Footprint (Top View)



S5 SERIES SIP or SMT Version Application Notes

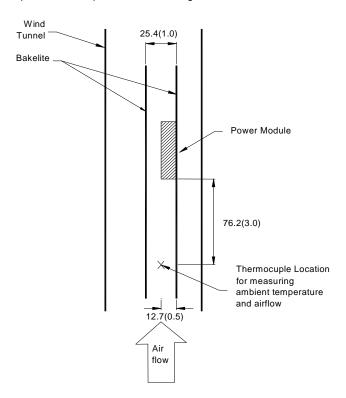
Applications
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- Servers, Switches and Data Storage
- Wireless Communications
- Distributed Power ArchitectureSemiconductor Test Equipment
- Data Communications
 - Telecommunications
 - Industrial / Medical

7.2 Convection Requirements for Cooling

To predict the approximate cooling needed for the module, refer to the Power De-rating curves in Figures 10 to 13 . These de-rating curves are approximations of the ambient temperatures and airflows required to keep the power module temperature below its maximum rating. Once the module is assembled in the actual system, the module's temperature should be checked as shown in Figure 7 to ensure it does not exceed 110°C.

Proper cooling can be verified by measuring the power module's temperature at Q1-pin 6 as shown in Figure 8,9.



Note: Dimensions are in millimeters and (inches)

Figure 7. Thermal Test Setup

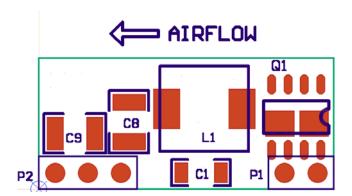


Figure 8. Temperature Measurement Location for SIP

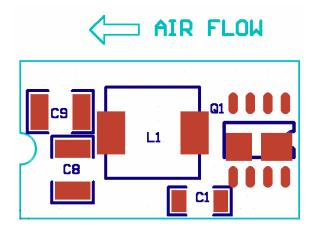


Figure 9. Temperature Measurement Location for SMT

7.3 Thermal Considerations

The power module operates in a variety of thermal environments; however, sufficient cooling should be provided to help ensure reliable operation of the unit. Heat is removed by conduction, convection, and radiation to the surrounding environment. The thermal data presented is based on measurements taken in a set-up as shown in Figure 7. Figures 10 to 13 represent the test data. Note that the airflow is parallel to the long axis of the module as shown in Figure 7 for the SIP/SMT. The temperature at either location should not exceed 110 °C. The output power of the module should not exceed the rated power for the module (VO, set x IO, max). The SMT Version of S5 Family thermal data presented is based on measurements taken in a wind tunnel. The test setup shown in Figure 7 and EUT need to solder on 33mm x 40.38mm(1.300" x 1.59") test pcb. Note that airflow is parallel to the long axis of the module as shown in Fig7.

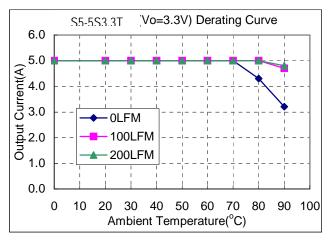


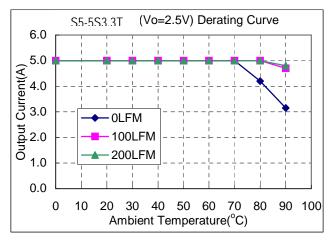
S5 SERIES SIP or SMT **Version Application Notes**

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7.4 Power De-Rating Curves





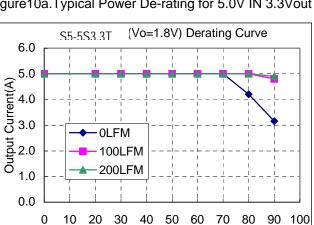


Figure 10a. Typical Power De-rating for 5.0V IN 3.3Vout Figure 10b. Typical Power De-rating for 5.0V IN 2.5Vout

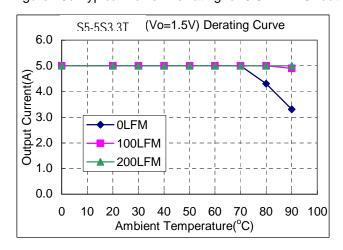


Figure 10c. Typical Power De-rating for 5.0V IN 1.8Vout

Ambient Temperature(°C)

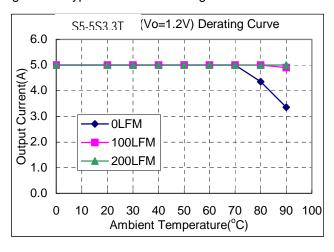


Figure 10d. Typical Power De-rating for 5.0V IN 1.5Vout

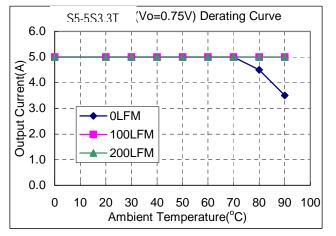


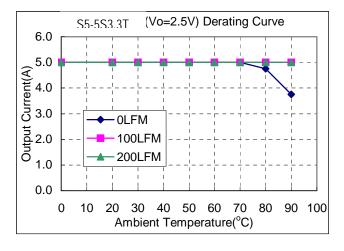
Figure 10e. Typical Power De-rating for 5.0V IN 1.2Vout Figure 10f. Typical Power De-rating for 5.0V IN 0.75Vout

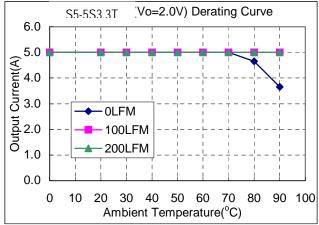


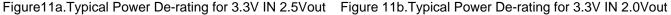
S5 SERIES SIP or SMT **Version Application Notes**

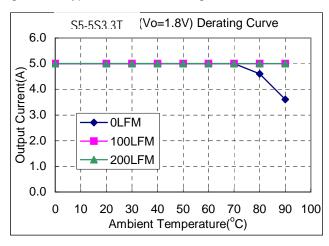
Applications

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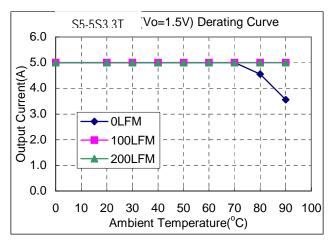
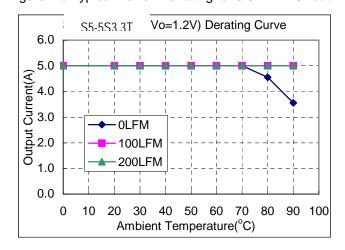


Figure11c.Typical Power De-rating for 3.3V IN 1.8Vout

Figure 11d. Typical Power De-rating for 3.3V IN 1.5Vout



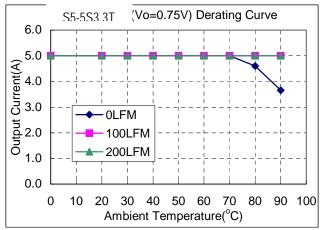


Figure 11e. Typical Power De-rating for 3.3V IN 1.2Vout Figure 11f. Typical Power De-rating for 3.3V IN 0.75Vout

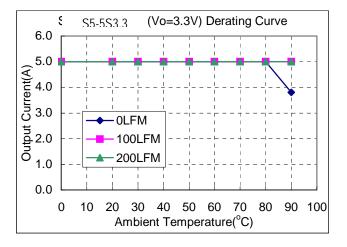


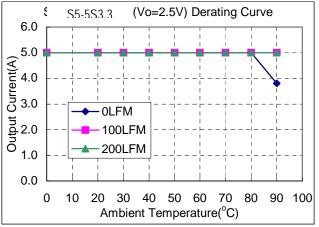
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S5 SERIES SIP or SMT **Version Application Notes**

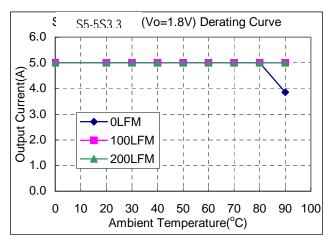
Applications

- Servers, Switches and Data Storage · Networking Gear Wireless Communications
- · Distributed Power Architecture
- Data Communications Telecommunications · Industrial / Medical
- Semiconductor Test Equipment









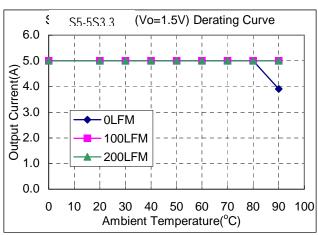
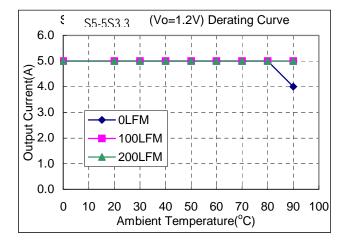


Figure 12c. Typical Power De-rating for 5V IN 1.8 Vout

Figure 12d. Typical Power De-rating for 5V IN 1.5Vout



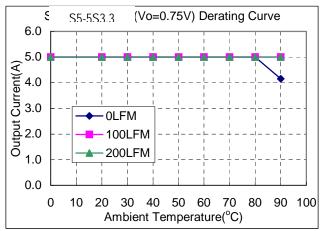


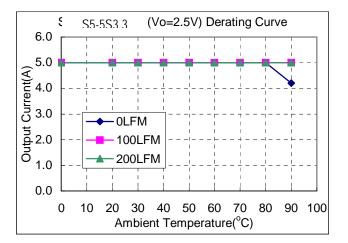
Figure 12e. Typical Power De-rating for 5V IN 1.2Vout Figure 12f. Typical Power De-rating for 5V IN 0.75Vout



S5 SERIES SIP or SMT **Version Application Notes**

Applications

- Servers, Switches and Data Storage
- Wireless Communications
- · Distributed Power Architecture Semiconductor Test Equipment · Industrial / Medical
- · Networking Gear Data Communications Telecommunications



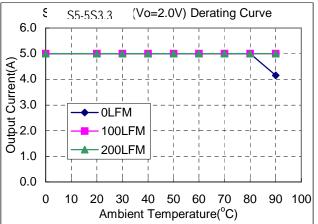
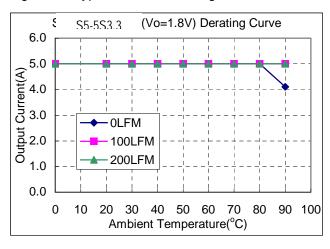


Figure 13a. Typical Power De-rating for 3.3V IN 2.5 Vout





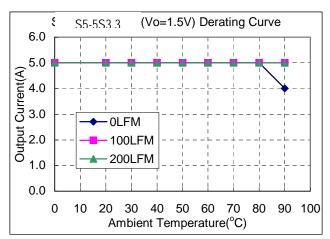
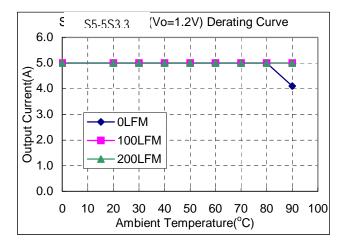


Figure 13c. Typical Power De-rating for 3.3V IN 1.8Vout

Figure 13d. Typical Power De-rating for 3.3V IN 1.5Vout



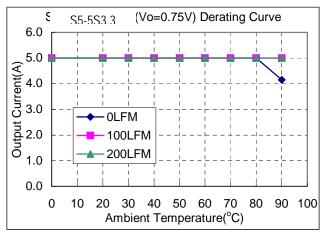


Figure 13e. Typical Power De-rating for 3.3V IN 1.2Vout Figure 13f. Typical Power De-rating for 3.3V IN 0.75Vout

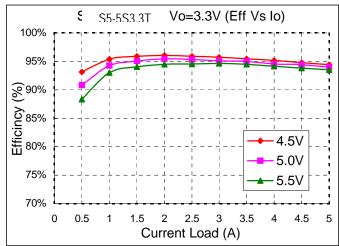


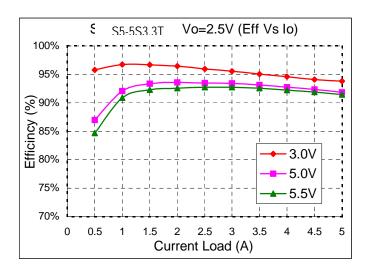
S5 SERIES SIP or SMT Version Application Notes

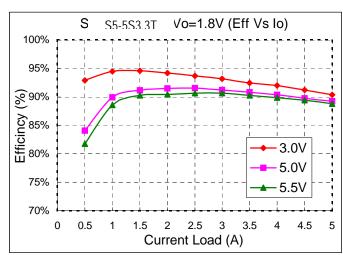
Applications

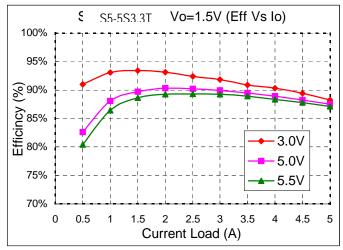
- Servers, Switches and Data Storage
- Wireless Communications
- Distributed Power Architecture
 Semiconductor Test Equipment
- Networking GearData CommunicationsTelecommunications
- Industrial / Medical

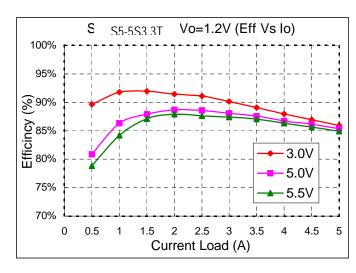
7.5 Efficiency vs Load Curves

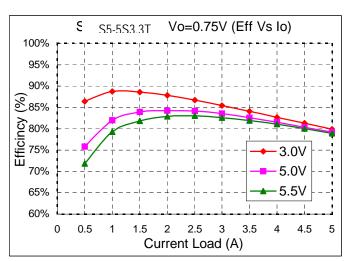














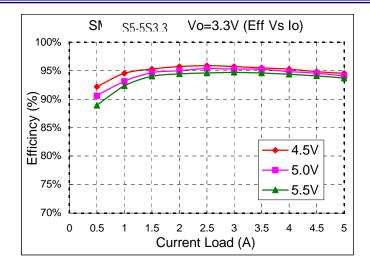
S5 SERIES SIP or SMT **Version Application Notes**

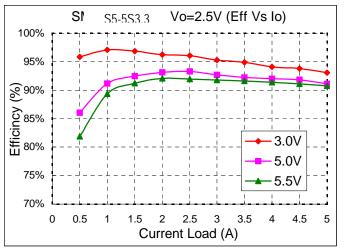
Applications

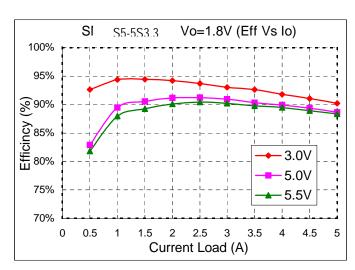
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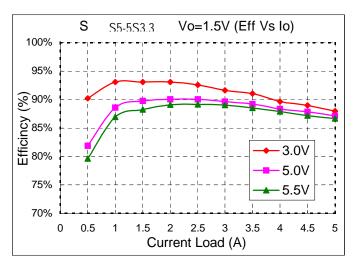
· Industrial / Medical

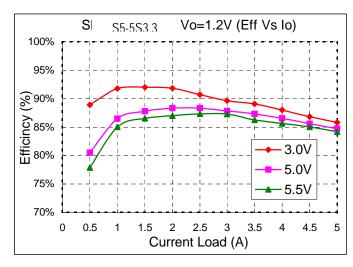
· Networking Gear

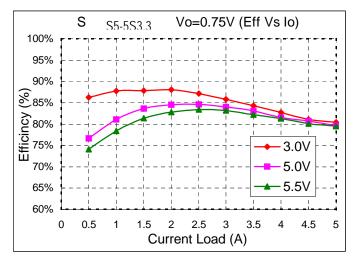














S5 SERIES SIP or SMT **Version Application Notes**

Applications · Networking Gear

- · Servers, Switches and Data Storage Wireless Communications
- · Distributed Power Architecture
- Semiconductor Test Equipment
- Data Communications
- Telecommunications
- · Industrial / Medical

7.6 Input Capacitance at the Power Module

The SIP/SMT converters must be connected to a low AC source impedance. To avoid problems with loop stability source inductance should be low. Also, the input capacitors should be placed close to the converter input pins to de-couple distribution inductance. However, the external input capacitors are chosen for suitable ripple handling capability. Low ESR polymers are a good choice. They have high capacitance, high ripple rating and low ESR (typical <100mohm). Electrolytic capacitors should be avoided. Circuit as shown in Figure 14 represents typical measurement methods for ripple current. Input reflected-ripple current is measured with a simulated source Inductance of 1uH. Current is measured at the input of the module.

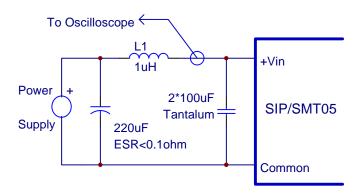


Figure 14. Input Reflected-Ripple Test Setup

7.7 Test Set-Up

The basic test set-up to measure parameters such as efficiency and load regulation is shown in Figure 15. Things to note are that this converter is non-isolated, as such the input and output share a common ground. These grounds should be connected together via low impedance ground plane in the application circuit. When testing a converter on a bench set-up, ensure that -Vin and -Vo are connected together via a low impedance short to ensure proper efficiency and load regulation measurements are being made. When testing the Intronics' S5 series under any transient conditions please ensure that the transient response of the source is sufficient to power the equipment under test. We can calculate the

- Efficiency
- Load regulation and line regulation.

The value of efficiency is defined as:

$$\eta = \frac{Vo \times Io}{Vin \times Iin} \times 100\%$$

Where: Vo is output voltage, lo is output current, Vin is input voltage, lin is input current.

The value of load regulation is defined as:

$$Load.reg = \frac{V_{FL} - V_{NL}}{V_{NL}} \times 100\%$$

Where: V_{FL} is the output voltage at full load V_{NL} is the output voltage at no load

The value of line regulation is defined as:

$$Line.reg = \frac{V_{HL} - V_{LL}}{V_{LL}} \times 100\%$$

Where: V_{HL} is the output voltage of maximum input voltage at full load. V_{LL} is the output voltage of minimum input voltage at full load.

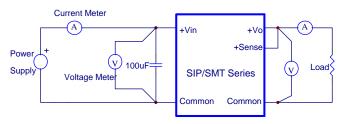


Figure 15. S5 Series Test Setup



S5 SERIES SIP or SMT Version Application Notes

- Applications
 Servers, Switches and Data Storage
- Wireless Communications
- Distributed Power Architecture
 Semiconductor Test Equipment
- Networking GearData Communications
 - Telecommunications
 - Industrial / Medical

7.8 S5 Series Output Voltage Adjustment.

The output Voltage of the S5 SERIES can be adjusted in the range 0.75V to 3.63V by connecting a single resistor on the motherboard (shown as Rtrim) in Figure 17. When Trim resistor is not connected the output voltage defaults to 0.75V

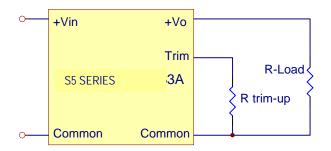


Figure 17. Trim-up Voltage Setup

The value of Rtrim-up defined as:

$$Rtrim = (\frac{21070}{V_0 - 0.75} - 5110)$$

Where: Rtrim-up is the external resistor in ohm,

Vo is the desired output voltage

To give an example of the above calculation, to set a voltage of 3.3Vdc, Rtrim is given by:

$$Rtrim = (\frac{21070}{V_0 - 0.75} - 5110)$$

Rtrim = 3153 ohm

For various output values various resistors are calculated and provided in Table 3 for convenience.

Vo,set (V)	Rtrim (Kohm)
0.75	Open
1.20	41.71
1.50	22.98
1.80	14.96
2.00	11.75
2.50	6.93
3.30	3.15
3.63	2.20

Table 3 - Trim Resistor Values

7.9 Output Ripple and Noise Measurement

The test set-up for noise and ripple measurements is shown in Figure 18. a coaxial cable with a 50ohm termination was used to prevent impedance mismatch reflections disturbing the noise readings at higher frequencies.

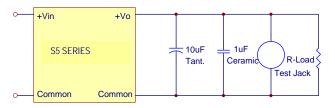


Figure 18. Output Voltage Ripple and Noise Measurement Set-Up

7.10 Output Capacitance

Intronics' S5 series converters provide unconditional stability with or without external capacitors. For good transient response low ESR output capacitors should be located close to the point of load. For high current applications point has already been made in layout considerations for low resistance and low inductance tracks. Output capacitors with its associated ESR values have an impact on loop stability and bandwidth. Intronics' converters are designed to work with load capacitance up-to 3,000uF. It is recommended that any additional capacitance, Maximum 3,000uF and low ESR, be connected close to the point of load and outside the remote compensation point.

7.11 SMT Reflow Profile

An example of the SMT reflow profile is given in Figure 19. **Equipment used:** SMD HOT AIR REFLOW HD-350SAR **Alloy:** AMQ-M293TA or NC-SMQ92 IND-82088 SN63

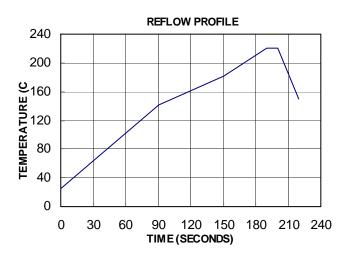


Figure 19 SMT Reflow Profile



S5 SERIES SIP or SMT **Version Application Notes**

Applications

- Servers, Switches and Data Storage · Networking Gear Wireless Communications Data Communications
- · Distributed Power Architecture
- · Semiconductor Test Equipment
- Telecommunications
 - · Industrial / Medical

8. Mechanical Outline Diagrams

8.1 S5 SERIES Mechanical Outline Diagrams

Dimensions are in millimeters and inches

Tolerance: x.xx ±0.02 in. (0.5mm), x.xxx ±0.010 in. (0.25 mm) unless otherwise noted

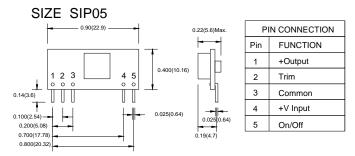


Figure 20 S5-5S3.3T Mechanical Outline Diagram

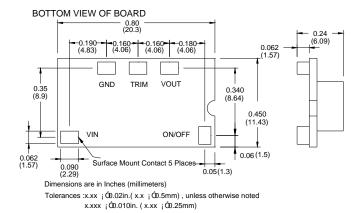
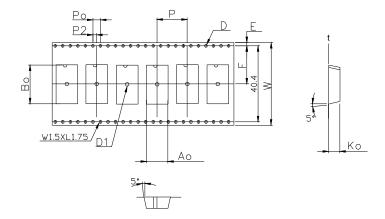


Figure 21 S5-5S3.3T Mechanical Outline Diagram

8.2 SMT Tape and Reel Dimensions

The Tape Reel dimensions for the SMT module is shown in Figure 22.



ITEM	SPEC
W	44.00 +0.30
Ao	11.50 +0.10
Во	20.70 +0.10
Ko	6.00 +0.10
P	16.00 +0.10
F	20.20 +0.10
Е	1.75 +0.10
D	1.50 +0.10 -0.00
D1	2.00 +0.25
Po	4.00 +0.10
P2	2.00 +0.10
t	0.35 +0.05

Figure 22 - SMT Tape and Reel Dimensions

S5 SERIES DC/DC MODULES

Applications Networking Gear

- · Servers, Switches and Data Storage Data Communications
- · Wireless Communications
- · Distributed Power Architecture
- Telecommunications
- · Semiconductor Test Equipment · Industrial / Medical

The S5 Family of high efficiency non-isolated DC/DC converters offer power levels of up to 25 Watt, while also providing ultra-wide input voltage range for 3.3Vin and 5Vin, as well, as 12Vin. These converters provide versatility without sacrificing the board space. All models feature an input filter and regulated outputs. The open-frame construction facilitates maximum power delivered with the highest efficiency of up to 92%. All converters combine creative design practices with highly derated power devices to achieve very high reliability, high performance and low cost solution to systems designers.

Specifications & Features Summary

- Industry Standard SIP and SMT Pinout
- High Efficiency to 92%
- 300KHz Switching Frequency
- Stable at all Loads
- Over Temperature Protection
- Adjustable Output Range Continuous Short Circuit Protection
- Remote ON/OFF
- UL/C-UL 60950 Certification Pending
- Add Suffix "T" for Through-Hole Model
- Add Suffix "N" for Negative Logic Control Version

A CHANGE

	MODEL	INPUT	OUTPUT	OUTPUT	INPUT C	URRENT	%	
	NUMBER	VOLTAGE	VOLTAGE	CURRENT	NO LOAD	FULL LOAD	EFF.	SIZE
ĺ	S5-5S3.3	3.0-5.5VDC	0.75- 3.63VDC	5 A	Various	Various	Various	SIP/SMT
1	S5-12S5	8.3-14VDC	0.75-5.0 VDC	5 A	Various	Various	Various	SIP/SMT

Typical at Ta= +25 °C under nominal input voltages of 3.3V, 5V and 12VDC, unless noted. The information and specifications contained in this brief are believed to be accurate and reliable at the time of publication. Specifications are subject to change without notice. Refer to product specification sheet for performance characteristics and application guidelines.

Consult factory for hundreds of other available input/output voltage configurations.

NOTE

- Measured From High Line to Low Line, Vo, set = 3.3Vdc Measured From Full Load to Zero Load, Vo, set = 3.3Vdc
- The output noise is measured with 10uf tantalum capacitor and 1uf ceramic capacitor across output.

 To reduce the input ripple voltage, parallel the Input Terminals with 47uF Capacitor and 10uF Ceramic 3.

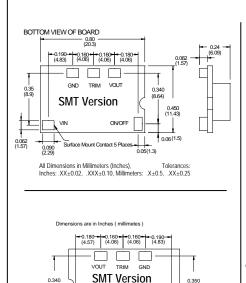
0.350

Megative Logic Remote on/off: Module ON: Open Circuit or < 0.4VDC Module OFF: 2.8VDC to Vin

Vo,set (V)	Rtrim (KΩ)
0.75	Open
1.2	22.33
1.5	13.0
1.8	9.0
2.0	7.4
2.5	5.00
3.3	3.12
5.0	1.47
T	

Table 1. External Resistor Values for programming output voltage

INPUT SPECIFICATIONS :	
Input Voltage Range 5V (12V)	3.0 – 5.5V (8.3 – 14.0V)
Positive Logic Remote on/off Control: Module ON Module OFF	Open Circuit or = Vin <0.4Vdc
Under Voltage Lock-out (12Vin) Power up Power down	8.0V typ. 7.9V typ.
Input Filter Type	Capacitive
OUTPUT SPECIFICATIONS :	
Voltage Accuracy	±1.5% max.
Transient Response: 25% Step Load Change	<200u sec.
Ripple and Noise 20MHz BW Note3 (5Vo)	20mV rms, 50mV pk-pk max. 45mVrms, 75Vpk-pk max.
Temperature Coefficient	±0.03%/°C max.
Short Circuit Protection	Continuous
Line Regulation, Note1	±0.2% max.
Load Regulation, Note2	±0.5% max.
Capacitive Load	Low ESR 3000uF max.
GENERAL SPECIFICATIONS :	
Efficiency	See App Notes
Isolation Voltage	Non-Isolated
Operating Ambient Temp. Range	-40°C to +85°C
Derating	See App Notes
Storage Temperature Range	-55°C to +125°C
Dimensions (SIP)	0.9"x0.4"x0.22"
	(22.9x10.16x5.6mm)
Dimensions (SMT)	0.8"x0.45"x0.24"
	(20.3x11.43x6.09mm)
Case Material	Non-potted Open Frame

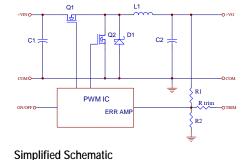


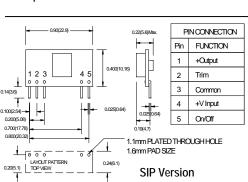
0.010 (0.25)

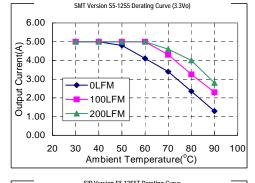
PAD SIZE

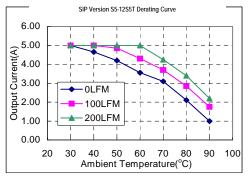
MIN: 0.120" x 0.095 " MAX: 0.135" x 0.110

0.340











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S10 SERIES SIP or SMT **Version Application Notes**

Applications

Wireless Communications

· Distributed Power Architecture

· Semiconductor Test Equipment

- Servers, Switches and Data Storage · Networking Gear
 - Data Communications
 - Telecommunications
 - · Industrial / Medical

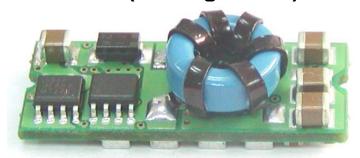
NON-ISOLATED DC-DC Converter

S10 SERIES 3.0-5.5Vin, 1-3.3Vout, 10A

APPLICATION NOTES Ver 1.0



S10-5SX.XT (Through-Hole) Series



S10-5SX.X SMT Series



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8.2 SMT Tape and Reel Dimensions

S10 SERIES SIP or SMT **Version Application Notes**

Applications

· Distributed Power Architecture

• Semiconductor Test Equipment

• Servers, Switches and Data Storage Networking Gear Data Communications Wireless Communications

Telecommunications

· Industrial / Medical

1. INTRODUCTION	3
2. MODELS	3
3. 10A SIP/SMT CONVERTER FEATURES	3
4. GENERAL DESCRIPTION	3
4.1 Electrical Description	3
4.2 Thermal Packaging and Physical Design.	4
5. MAIN FEATURES AND FUNCTIONS	4
5.1 Operating Temperature Range	4
5.2 Over-Temperature Protection (OTP)	4
5.3 Output Voltage Adjustment	4
5.4 Safe Operating Area (SOA)	4
5.5 Over Current Protection	4
5.6 Remote ON/OFF	4
5.7 UVLO (Under-Voltage Lockout)	5
6. SAFETY	5
6.1 Input Fusing and Safety Considerations.	5
7. APPLICATIONS	5
7.1 Layout Design Challenges.	5
7.2 Convection Requirements for Cooling	6
7.3 Thermal Considerations	6
7.4 Power De-Rating Curves	7
7.5 Input Capacitance at the Power Module	7
7.6 Test Set-Up	8
7.7 Remote Sense Compensation	8
7.8 S10-5SX.X Series Output Voltage Adustment.	8
7.9 Output Ripple and Noise Measurement	10
7.10 Output Capacitance	10
7.11 SMT Reflow Profile	10
8. MECHANICAL OUTLINE DIAGRAMS	10
8.1 SIP/SMT S10 Mechanical Outline Diagrams	10

11



S10 SERIES SIP or SMT Version Application Notes

Applications

• Servers, Switches and Data Storage • Networking Gear

Wireless Communications
Distributed Power Architecture
Telecomm

· Semiconductor Test Equipment

• Data Communications

Telecommunications

Industrial / Medical

1. Introduction

This application note describes the features and functions of Intronics' S10 SMT series of Non Isolated DC-DC Converters. These are highly efficient, reliable and compact, high power

density, single output DC/DC converters. These "Point of Load" modules serve the needs specifically of the fixed and mobile telecommunications and computing market, employing economical distributed Power Architectures.

The S10 SMT series provide precisely regulated output voltage range from 1.0V to 3.3Vdc over a wide range of input voltage (Vi=3.0 – 5.5Vdc) and can operate over an ambient temperature range of –40C to +85C. Ultra-high efficiency operation is achieved through the use of synchronous rectification and drive control techniques. The modules are fully protected against short circuit and over-temperature conditions.

Intronics' world class automated manufacturing methods, together with an extensive testing and qualification program, ensure that all S10-5SX.X series converters are extremely reliable.

2. Models

The adjustable S10 series currently comprises of 7 models.

Model	Input Voltage	Output Voltage	Output Current
S10-5S1.0T	3.0 - 5.5VDC	1.0V	10A
S10-5S1.2T	3.0 – 5.5VDC	1.2V	10A
S10-5S1.5T	3.0 – 5.5VDC	1.5V	10A
S10-5S1.8T	3.0 – 5.5VDC	1.8V	10A
S10-5S2.5T	3.0 – 5.5VDC	2.0V	10A
S10-5S3.3T	3.0 – 5.5VDC	2.5V	10A
S10-5S5.0T	4.5 – 5.5VDC	3.3V	10A

Table 1A – S10-5SX.XT Through-Hole Series Models

The adjustable SMT10-05 series comprises of 7 models.

Model	Input Voltage	Output Voltage	Output Current
040 504 0	•	•	
S10-5S1.0	3.0 – 5.5VDC	1.0V	10A
S10-5S1.2	3.0 – 5.5VDC	1.2V	10A
S10-5S1.5	3.0 – 5.5VDC	1.5V	10A
S10-5S1.8	3.0 – 5.5VDC	1.8V	10A
S10-5S2.5	3.0 – 5.5VDC	2.0V	10A
S10-5S3.3	3.0 – 5.5VDC	2.5V	10A
S10-5S5.0	4.5 – 5.5VDC	3.3V	10A

Table 1B - S10-5SX X SMT Series Models

3. 10A SIP/SMT Converter Features

- High efficiency topology, typically 95% at 3.3Vdc
- Industry standard footprint
- Wide ambient temperature range, -40C to +85C
- · Cost efficient open frame design
- ±10% output voltage trimmable.
- No minimum load requirement (Stable at all loads)
- Remote ON/OFF
- Remote sense compensation
- · Fixed switching frequency
- Continuous short-circuit protection and over current protection
- Over-temperature protection (OTP)
- Monotonic Startup with pre-bias at the output.
- UL/IEC/EN60950 Certified.

4. General Description

4.1 Electrical Description

A block diagram of the S10-5SX.X Series converter is shown in Figure 1. Extremely high efficiency power conversion is achieved through the use of synchronous rectification and drive techniques.

Essentially, the powerful S10-5SX.X series topology is based on a non-isolated synchronous buck converter. The control loop is optimized for unconditional stability, fast transient response and a very tight line and load regulation. In a typical pre-bias application the S10-5SX.X series converters do not draw any reverse current at start-up. The output is adjustable over a range of -10% to +10% of the nominal output voltage, using the TRIM pin.

The converter can be shut down via a remote ON/OFF input that is referenced to ground. This input is compatible with popular logic devices; a 'negative' logic input is supplied as standard. Negative logic implies that the converter is enabled if the remote ON/OFF input is low (or floating), and disabled if it is high.

The converter is also protected against over-temperature conditions. If the converter is overloaded or the ambient temperature gets too high, the converter will shut down to protect the unit.

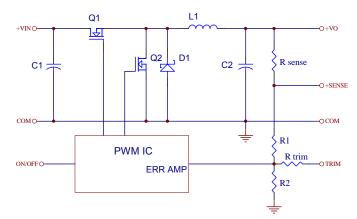


Figure 1. Electrical Block Diagram



S10 SERIES SIP or SMT **Version Application Notes**

Applications

- · Servers, Switches and Data Storage · Networking Gear Data Communications
- Wireless Communications
- · Distributed Power Architecture
- Semiconductor Test Equipment
- Telecommunications
- · Industrial / Medical

4.2 Thermal Packaging and Physical Design.

The S10-5SX.X series uses a multi-layer FR4 PCB construction. All surface mount power components are placed on one side of the PCB, and all low-power control components are placed on the other side. Thus, the Heat dissipation of the power components is optimized, ensuring that control components are not thermally stressed. The converter is an open-frame product and has no case or case pin. The open-frame design has several advantages over encapsulated closed devices. Among these advantages are:

- Efficient Thermal Management: the heat is removed from the heat generating components without heating more sensitive, small signal control components.
- Environmental: Lead free open-frame converters are more easily re-cycled.
- Cost Efficient: No encapsulation. Cost efficient open-frame construction.
- Reliable: Efficient cooling provided by open frame construction offers high reliability and easy diagnostics.

5. Main Features and Functions

5.1 Operating Temperature Range

Intronics' S10-5SX.X series converters highly efficient converter design has resulted in its ability to operate over a wide ambient temperature environment (-40C to 85C). Due consideration must be given to the de-rating curves when ascertaining maximum power that can be drawn from the converter. The maximum power drawn is influenced by a number of factors, such as:

- Input voltage range.
- Output load current.
- Air velocity (forced or natural convection).
- Mounting orientation of converter PCB with respect to the Airflow.
- Motherboard PCB design, especially ground and power planes. These can be effective heatsinks for the converter.

5.2 Over-Temperature Protection (OTP)

The S10-5SX.X Series converters are equipped with non-latching overtemperature protection. A temperature sensor monitors the temperature of the hot spot (typically, top switch). If the temperature exceeds a threshold of 120°C (typical) the converter will shut down, disabling the output. When the temperature has decreased the converter will automatically restart.

The over-temperature condition can be induced by a variety of reasons such as external overload condition or a system fan failure.

5.3 Output Voltage Adjustment

Section 7.8 describes in detail as to how to trim the output voltage with respect to its set point. The output voltage on all models is trimmable in the range -10% to +10%.

5.4 Safe Operating Area (SOA)

Figure 2 provides a graphical representation of the Safe Operating Area (SOA) of the converter. This representation assumes ambient operating conditions such as airflow are met as per thermal guidelines provided in Sections 7.2 and 7.3.

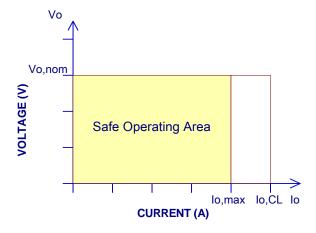


Figure 2. Maximum Output Current Safe Operating Area

5.5 Over Current Protection

All different voltage models have a full continuous short-circuit protection. The unit will auto recover once the short circuit is removed. To provide protection in a fault condition, the unit is equipped with internal over-current protection. The unit operates normally once the fault condition is removed. The power module will supply up to 170% of rated current. In the event of an over current converter will go into a hiccup mode protection.

5.6 Remote ON/OFF

The remote ON/OFF input feature of the converter allows external circuitry to turn the converter ON or OFF. Active-low remote ON/OFF is available as standard

The S10-5SX.X series converters are turned on if the remote ON/OFF pin is low, or left open or floating. Pulling the pin high will turn the converter 'Off'. The signal level of the remote on/off input is defined with respect to ground. The unit is guaranteed OFF over the full temperature range if this voltage level exceeds 2.8Vdc.

The remote ON/OFF input can be driven as described in Figure 3.



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+Vin +Vo SIP10 Series ON/OFF Control Remote ON/OFF Common Common

Figure 3. Remote ON/OFF Input Drive Circuit

5.7 UVLO (Under-Voltage Lockout)

The voltage on the Vcc pin determines the start of the operation of the Converter. When the input Vcc rises and exceeds about 2.8V the converter initiates a soft start. The UVLO function in the converter has a Hysterisis (about 100mV) built in to provide noise immunity at start-

6. Safety

6.1 Input Fusing and Safety Considerations.

Agency Approvals: The power Supply shall be submitted to and receive formal approval from the following test agencies.

- 1. The power supply shall be approved by a nationally recognized testing laboratory to UL/CSA 60950 3rd Edition (North America) and EN60950 (International)
- 2. CB Certificate from an internationally recognized test house in accordance with EN 60950.

The S10-5SX.X series converters do not have an internal fuse. However, to achieve maximum safety and system protection, always use an input line fuse. The safety agencies require a time-delay fuse with a maximum rating of 20A.

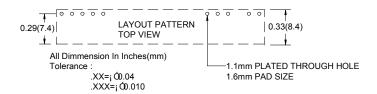
7. Applications

7.1 Layout Design Challenges.

In optimizing thermal design the PCB is utilized as a heatsink. Also some heat is transferred from the SIP module to the main board through connecting pins. The system designer or the end user must ensure that other components and metal in the vicinity of the S10-5SX.X series SIP's meet the spacing requirements to which the system is approved.

Low resistance and low inductance PCB layout traces are the norm and should be used where possible. Due consideration must also be

given to proper low impedance tracks between power module, input and output grounds.



VIEW IS FROM TOP SIDE Figure 4A. Recommended SIP Footprint

Recommended Pad Layout

Dimensions are in millimetes and(inches)

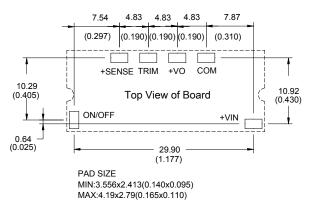


Figure 4B. Recommended SMT Footprint



S10 SERIES SIP or SMT **Version Application Notes**

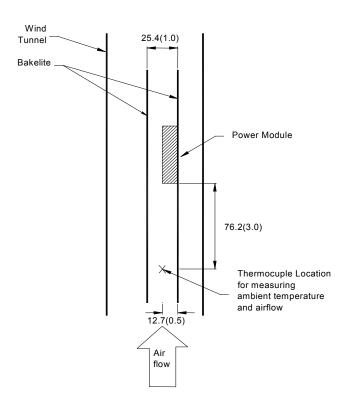
Applications

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- Telecommunications
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7.2 Convection Requirements for Cooling

To predict the approximate cooling needed for the module, refer to the Power De-rating curves in Figures 9 and 10. These de-rating curves are approximations of the ambient temperatures and airflows required to keep the power module temperature below its maximum rating. Once the module is assembled in the actual system, the module's temperature should be checked as shown in Figure 5 to ensure it does not exceed 110°C.

Proper cooling can be verified by measuring the power module's temperature at Q1-pin 6 and Q2-pin 6 as shown in Figure 6A,6B.



Note: Dimensions are in millimeters and (inches)

Figure 5. Thermal Test Setup

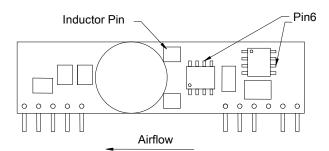


Figure 6A. Temperature Measurement Location for SIP

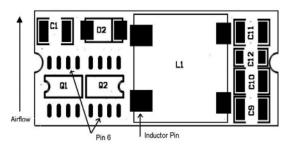


Figure 6B. Temperature Measurement Location for SMT

7.3 Thermal Considerations

The power module operates in a variety of thermal environments; however, sufficient cooling should be provided to help ensure reliable operation of the unit. Heat is removed by conduction, convection, and radiation to the surrounding environment. The thermal data presented is based on measurements taken in a set-up as shown in Figure 5. Figures 7A,7B and 8A,8B represent the test data.

Note that the airflow is parallel to the long axis of the module as shown in Figure 6A for the SIP.

The temperature at either location should not exceed 110 °C. The output power of the module should not exceed the rated power for the module (VO, set x IO, max).

The SMT10 thermal data presented is based on measurements taken in a wind tunnel. The test setup shown in Figure 5 and EUT need to solder on 33mm x 40.38mm(1.300" x 1.59") test pcb. Note that airflow is parallel to the long axis of the module as shown in Fig 6B



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7.4 Power De-Rating Curves

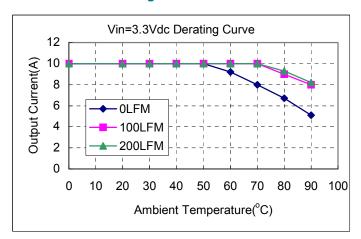


Figure 7A Typical Power De-rating for 3.3V IN(SIP10)

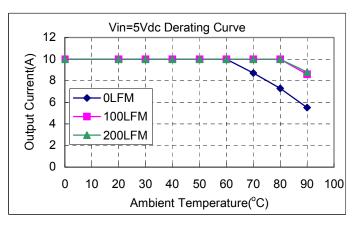


Figure 7B. Typical Power De-rating for 5.0V IN(SIP10)

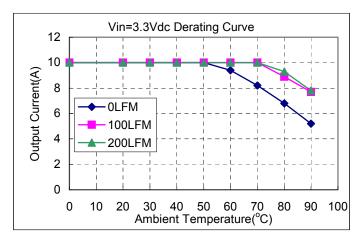
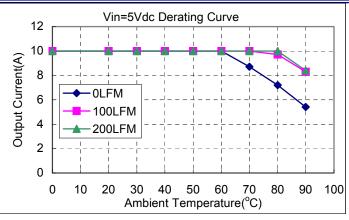


Figure 8A. Typical Power De-rating for 3.3V IN (SMT10)



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· Semiconductor Test Equipment

Figure8B.Typical Power De-rating for 5.0V IN(SMT10)

7.5 Input Capacitance at the Power Module

The SIP/SMT converters must be connected to a low AC source impedance. To avoid problems with loop stability source inductance should be low. Also, the input capacitors should be placed close to the converter input pins to de-couple distribution inductance. However, the external input capacitors are chosen for suitable ripple handling capability. Low ESR polymers are a good choice. They have high capacitance, high ripple rating and low ESR (typical $<20m\Omega$). Electrolytic capacitors should be avoided. Circuit as shown in Figure 9 represents typical measurement methods for ripple current. Input reflected-ripple current is measured with a simulated source Inductance of 1uH. Current is measured at the input of the module.

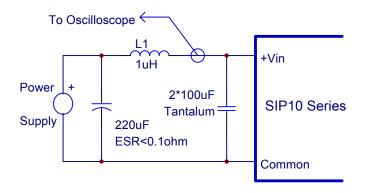


Figure 9. Input Reflected-Ripple Test Setup



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7.6 Test Set-Up

The basic test set-up to measure parameters such as efficiency and load regulation is shown in Figure 10. Things to note are that this converter is non-isolated, as such the input and output share a common ground. These grounds should be connected together via low impedance ground plane in the application circuit. When testing a converter on a bench set-up, ensure that -Vin and -Vo are connected together via a low impedance short to ensure proper efficiency and load regulation measurements are being made. When testing the Intronics' S10-5SX.X series under any transient conditions please ensure that the transient response of the source is sufficient to power the equipment under test. We can calculate the

- Efficiency
- Load regulation and line regulation.

The value of efficiency is defined as:

$$\eta = \frac{Vo \times Io}{Vin \times Iin} \times 100\%$$

Where: Vo is output voltage,

lo is output current,

Vin is input voltage, lin is input current.

The value of load regulation is defined as:

$$Load.reg = \frac{V_{FL} - V_{NL}}{V_{NL}} \times 100\%$$

Where: V_{FL} is the output voltage at full load

V_{NL} is the output voltage at no load

The value of line regulation is defined as:

$$Line.reg = \frac{V_{HL} - V_{LL}}{V_{LL}} \times 100\%$$

Where: V_{HL} is the output voltage of maximum input voltage at full load. V_{LL} is the output voltage of minimum input voltage at full load.

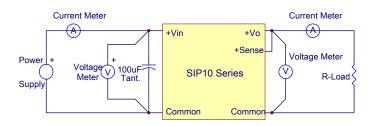


Figure 10. SIP10 Series Test Setup

7.7 Remote Sense Compensation

Remote Sense regulates the output voltage at the point of load. It minimizes the effects of distribution losses such as drops across the connecting pin and PCB tracks (see Figure 11). Please note however, the maximum drop from the output pin to the point of load should not exceed 500mV for remote compensation to work.

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The amount of power delivered by the module is defined as the output voltage multiplied by the output current (VO x IO).

When using TRIM UP, the output voltage of the module will increase which, if the same output current is maintained, increases the power output by the module. Make sure that the maximum output power of the module remains at or below the maximum rated power.

When the Remote Sense feature is not being used, leave sense pin disconnected.

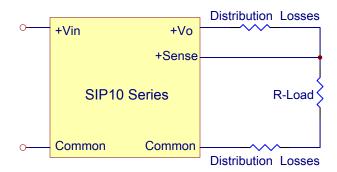


Figure 11. Circuit Configuration for Remote Sense Operation

7.8 S10-5SX.X Series Output Voltage Adustment.

In order to trim the voltage up or down one needs to connect the trim resistor either between the trim pin and ground for trim-up and between trim pin and Vsense+ for trim-down. The output voltage trim range is ±10%. This is shown in Figures 12 and 13:

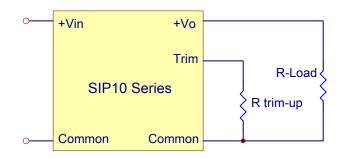


Figure 12. Trim-up Voltage Setup



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Applications

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Data Communications

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+Vin +Vo R trim-down SIP10 Series R-Load Trim Common Common

Figure 13. Trim-down Voltage Setup

The value of Rtrim-up defined as:

$$R_{trim - up} = \left(\frac{R1 \times 0.8}{V_O - V_{o, nom}}\right) - Rt \text{ (K}\Omega)$$

Where: Rtrim-up is the external resistor in $K\Omega$.

Vo,nom is the nominal output voltage.

Vo is the desired output voltage.

R1 and Rt are internal to the unit and are defined in Table 2.

Output Voltage(V)	R1 (KΩ)	Rt (KΩ)
1.0	30.1	30.1
1.2	30.1	59
1.5	30.1	100
1.8	30.1	100
2.0	30.1	100
2.5	30.1	78.7
3.3	30.1	59

Table 2 - Trim Resistor Values

For example, to trim-up the output voltage of 1.5V module (SIP10-05S15E) by 8% to 1.62V, Rtrim-up is calculated as follows:

$$Vo - Vo,nom = 1.62 - 1.5 = 0.12V$$

Rt = 100 K Ω

R1= $30.1 \text{ K}\Omega$

$$R_{trim-up} = \frac{30.1 \times 0.8}{0.12} - 100 = 100.66 \text{ (K}\Omega)$$

The value of Rtrim-down defined as:

$$R_{trim-down} = \frac{R1 \times (Vo - 0.8)}{V_{o,nom} - Vo} - Rt \text{ (K}\Omega)$$

Where: Rtrim-down is the external resistor in $K\Omega$.

Vo,nom is the nominal output voltage.

Vo is the desired output voltage.

R1 and Rt are internal to the unit and are defined in Table 2.

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For example, to trim-down the output voltage of 2.5V module (SIP10-05S25E) by 8% to 2.3V, Rtrim-down is calculated as follows:

$$Vo,nom - Vo = 2.5 - 2.3 = 0.2 V$$

R1 = 30.1 KΩ

$$R_{trim-down} = \frac{30.1 \times (2.3 - 0.8)}{0.2} - 78.7 = 147.05 \text{ (K}\Omega)$$

For Trim-up using an external voltage source, apply a voltage from TRIM pin to ground using the following equation:

$$V_{trim-up} = 0.8 - \left(\frac{(Vo - V_{o, nom}) \times Rt}{R1}\right)$$

For Trim-down using an external voltage source, apply a voltage from TRIM pin to ground using the following equation:

$$V_{trim-down} = 0.8 + \frac{(V_{O,nom} - V_{O}) \times Rt}{R1}$$

Vtrim-up is the external source voltage for trim-up.

Vtrim-down is the external source voltage for trim-down.

Vo is the desired output voltage.

Vo,nom is the nominal output voltage.

Rt (internal to the module) is defined in Table 2.

If the TRIM feature is not being used, leave the TRIM pin disconnected.



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7.9 Output Ripple and Noise Measurement

The test set-up for noise and ripple measurements is shown in Figure 14. a 50Ω . coaxial cable with a 50Ω termination was used to prevent impedance mismatch reflections disturbing the noise readings at higher frequencies.

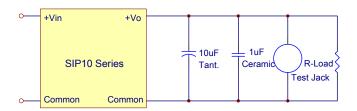


Figure 14. Output Voltage Ripple and Noise Measurement Set-Up

7.10 Output Capacitance

Intronics' S10-5SX.X series converters provide unconditional stability with or without external capacitors. For good transient response low ESR output capacitors should be located close to the point of load. For high current applications point has already been made in layout considerations for low resistance and low inductance tracks.

Output capacitors with its associated ESR values have an impact on loop stability and bandwidth. Intronics' converters are designed to work with load capacitance up-to 10,000uF. It is recommended that any additional capacitance, typically 1,000uF and low ESR (<20mΩ), be connected close to the point of load and outside the remote compensation point.

7.11 SMT Reflow Profile

An example of the SMT reflow profile is given in Figure 15.

Equipment used: SMD HOT AIR REFLOW HD-350SAR Alloy: AMQ-M293TA or NC-SMQ92 IND-82088 SN63

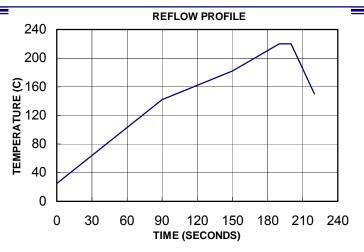


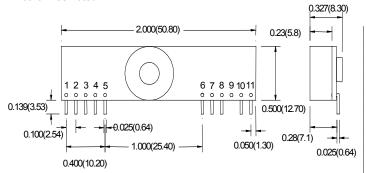
Figure 15 - SMT Reflow Profile

8. Mechanical Outline Diagrams

8.1 SIP/SMT10 Mechanical Outline Diagrams

Dimensions are in millimeters and (inches)

Tolerance: x.xx ±0.02 in.(0.5mm), x.xxx ±0.010 in. (0.25 mm) unless otherwise noted



PIN CONNECTION		
Pin	FUNCTION	
1	+Output	
2	+Output	
3	+Sense	
4	+Output	
5	Common	
6	Common	
7	+V Input	
8	+V Input	
9	No Pin	
10	Trim	
11	On/Off Control	

Figure 16. SIP10 Mechanical Outline Diagram

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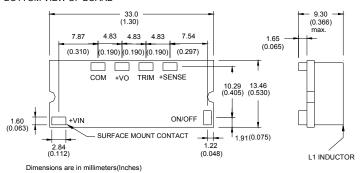
Applications

- · Servers, Switches and Data Storage · Networking Gear
- Wireless Communications Data Communications · Distributed Power Architecture

· Semiconductor Test Equipment

- Telecommunications
- · Industrial / Medical

BOTTOM VIEW OF BOARD



 $Tolerances: X.X_{\dot{1}} \, \acute{\textbf{0}}0.5 mm (0.02 in), X.XX_{\dot{1}} \, \acute{\textbf{0}}0.25 mm (0.010 in), unless otherwise noted.$

Figure 17. SMT10 Mechanical Outline Diagram

8.2 SMT Tape and Reel Dimensions

The Tape Reel dimensions for the SMT module is shown in Figure 18.

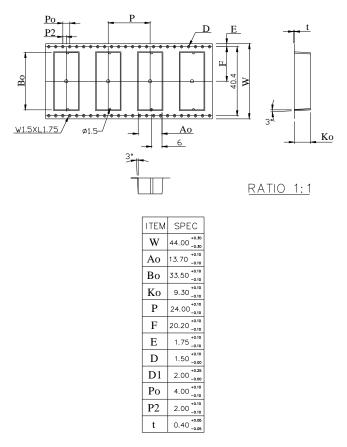


Figure 18 - SMT Tape and Reel Dimensions



S15 SERIES SIP or SMT Version Application Notes

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- Data Communications
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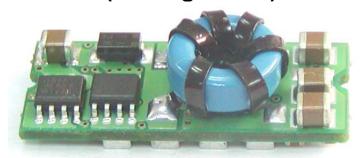
NON-ISOLATED DC-DC Converter

S15 SIP / SMT SERIES 3.0-5.5Vin, 0.9-3.63Vout, 15A

APPLICATION NOTES
Ver 1.0



S15-5S3.3T (Through-Hole) Converter



S15-5S3.3 SMT Version Converter



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Applications
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1. INTRODUCTION	3
2. MODELS	3
3. 15A SIP/SMT CONVERTER FEATURES	3
4. GENERAL DESCRIPTION	3
4.1 Electrical Description	3
4.2 Thermal Packaging and Physical Design.	4
5. MAIN FEATURES AND FUNCTIONS	4
5.1 Operating Temperature Range	4
5.2 Over-Temperature Protection (OTP)	4
5.3 Output Voltage Adjustment	4
5.4 Safe Operating Area (SOA)	4
5.5 Over Current Protection	4
5.6 Remote ON/OFF	4
5.7 UVLO (Under-Voltage Lockout)	5
6. SAFETY	5
6.1 Input Fusing and Safety Considerations.	5
7. APPLICATIONS	5
7.1 Layout Design Challenges.	5
7.2 Convection Requirements for Cooling	6
7.3 Thermal Considerations	6
7.4 Power De-Rating Curves	7
7.5 Input Capacitance at the Power Module	7
7.6 Test Set-Up	8
7.7 Remote Sense Compensation	8
7.8 S15-5S3.3 Output Voltage Adustment.	8
7.9 Output Ripple and Noise Measurement	9
7.10 Output Capacitance	9
7.11 SMT Reflow Profile	9
8. MECHANICAL OUTLINE DIAGRAMS	10
8.1 SIP/SMT15 Mechanical Outline Diagrams	10
8.2 SMT Tape and Reel Dimensions	10



S15 SERIES SIP or SMT **Version Application Notes** **Applications**

 Servers, Switches and Data Storage Networking Gear

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- Wireless Communications Data Communications · Distributed Power Architecture
 - Telecommunications
 - · Industrial / Medical

1. Introduction

This application note describes the features and functions of Intronics' S15-5S3.3 of Non Isolated DC-DC Converters. These are highly efficient, reliable and compact, high power density, single output DC/DC converters. These "Point of Load" modules serve the needs specifically of the fixed and mobile telecommunications and computing market, employing economical distributed Power Architectures.

The S15-5S3.3 provide precisely regulated output voltage range from 0.9V to 3.63Vdc over a wide range of input voltage (Vi=3.0 – 5.5Vdc) and can operate over an ambient temperature range of -40C to +85C. Ultra-high efficiency operation is achieved through the use of synchronous rectification and drive control techniques. The modules are fully protected against short circuit and over-temperature conditions.

Intronics' world class automated manufacturing methods, together with an extensive testing and qualification program, ensure that all S15-5S3.3 converters are extremely reliable.

2. Models

The adjustable S15-5S3.3 series models are shown in table1:

Model	Input Voltage	Output Voltage	Output Current
S15-5S3.3T	•	0.9 – 3.63VDC	15A
S15-5S3.3	3.0 - 5.5VDC	0.9 - 3.63VDC	15A

Table 1 - 15A SIP/SMT Models

3. S15-5S3.3 Converter Features

- High efficiency topology, typically 94% at 3.3Vdc
- Industry standard footprint
- Wide ambient temperature range, -40C to +85C
- Cost efficient open frame design
- Programmable output voltage via external resistor from 0.9 to 3.63Vdc
- No minimum load requirement (Stable at all loads)
- Remote ON/OFF
- Remote sense compensation
- Fixed switching frequency
- Continuous short-circuit protection and over current protection
- Over-temperature protection (OTP)
- Monotonic Startup with pre-bias at the output.
- UL/IEC/EN60950 Certified.

General Description

4.1 Electrical Description

A block diagram of the S15-5S3.3 converter is shown in Figure 1. Extremely high efficiency power conversion is achieved through the use of synchronous rectification and drive techniques. Essentially, the powerful S15-5S3.3 topology is based on a non-isolated synchronous buck converter. The control loop is optimized for unconditional stability, fast transient response and a very tight line and load regulation. In a typical pre-bias application the S15-5S3.3 converters do not draw any reverse current at start-up.

The output voltage can be adjusted from 0.9 to 3.63vdc, using the TRIM pin with a external resistor.

The converter can be shut down via a remote ON/OFF input that is referenced to ground. This input is compatible with popular logic devices; a 'negative' logic input is supplied as standard. Negative logic implies that the converter is enabled if the remote ON/OFF input is low (or floating), and disabled if it is high.

The converter is also protected against over-temperature conditions. If the converter is overloaded or the ambient temperature gets too high. the converter will shut down to protect the unit.

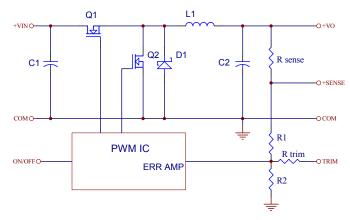


Figure 1. Electrical Block Diagram



S15 SERIES SIP or SMT **Version Application Notes**

Applications Networking Gear

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- Wireless Communications Data Communications
- · Distributed Power Architecture · Semiconductor Test Equipment
- Telecommunications
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4.2 Thermal Packaging and Physical Design.

The S15-5S3.3 uses a multi-layer FR4 PCB construction. All surface mount power components are placed on one side of the PCB, and all low-power control components are placed on the other side. Thus, the Heat dissipation of the power components is optimized, ensuring that control components are not thermally stressed.

The converter is an open-frame product and has no case or case pin. The open-frame design has several advantages over encapsulated closed devices. Among these advantages are:

- Efficient Thermal Management: the heat is removed from the heat generating components without heating more sensitive, small signal control components.
- Environmental: Lead free open-frame converters are more easily re-cycled.
- Cost Efficient: No encapsulation. Cost efficient open-frame construction.
- Reliable: Efficient cooling provided by open frame construction offers high reliability and easy diagnostics.

5. Main Features and Functions

5.1 Operating Temperature Range

Intronics' S15-5S3.3 converters highly efficient converter design has resulted in its ability to operate over a wide ambient temperature environment (-40C to 85C). Due consideration must be given to the de-rating curves when ascertaining maximum power that can be drawn from the converter. The maximum power drawn is influenced by a number of factors, such as:

- Input voltage range.
- Output load current.
- Air velocity (forced or natural convection).
- Mounting orientation of converter PCB with respect to the Airflow.
- Motherboard PCB design, especially ground and power planes. These can be effective heatsinks for the converter.

5.2 Over-Temperature Protection (OTP)

The S15-5S3.3 converters are equipped with non-latching overtemperature protection. A temperature sensor monitors the temperature of the hot spot (typically, top switch). If the temperature exceeds a threshold of 120°C (typical) the converter will shut down, disabling the output. When the temperature has decreased the converter will automatically restart.

The over-temperature condition can be induced by a variety of reasons such as external overload condition or a system fan failure.

5.3 Output Voltage Adjustment

Section 7.8 describes in detail as to how to trim the output voltage with respect to its set point. The output voltage on all models is trimmable in the range 0.9 - 3.63Vdc.

5.4 Safe Operating Area (SOA)

Figure 2 provides a graphical representation of the Safe Operating Area (SOA) of the converter. This representation assumes ambient operating conditions such as airflow are met as per thermal guidelines provided in Sections 7.2 and 7.3.

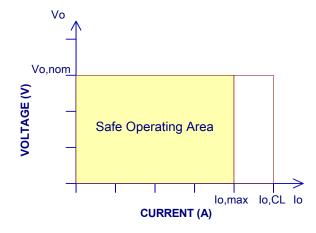


Figure 2. Maximum Output Current Safe Operating Area

5.5 Over Current Protection

All different voltage models have a full continuous short-circuit protection. The unit will auto recover once the short circuit is removed. To provide protection in a fault condition, the unit is equipped with internal over-current protection. The unit operates normally once the fault condition is removed. The power module will supply up to 140% of rated current. In the event of an over current converter will go into a hiccup mode protection.

5.6 Remote ON/OFF

The remote ON/OFF input feature of the converter allows external circuitry to turn the converter ON or OFF. Active-low remote ON/OFF is available as standard.

The S15-5S3.3 converters are turned on if the remote ON/OFF pin is low, or left open or floating. Pulling the pin high will turn the converter 'Off'. The signal level of the remote on/off input is defined with respect to ground. The unit is guaranteed OFF over the full temperature range if this voltage level exceeds 2.8Vdc.

The remote ON/OFF input can be driven as described in Figure 3.



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Applications · Networking Gear

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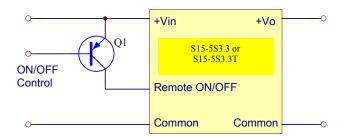


Figure 3. Remote ON/OFF Input Drive Circuit

5.7 UVLO (Under-Voltage Lockout)

The voltage on the Vcc pin determines the start of the operation of the Converter. When the input Vcc rises and exceeds about 2.8V the converter initiates a soft start. The UVLO function in the converter has a Hysterisis (about 100mV) built in to provide noise immunity at start-

6. Safety

6.1 Input Fusing and Safety Considerations.

Agency Approvals: The power Supply shall be submitted to and receive formal approval from the following test agencies.

- 1. The power supply shall be approved by a nationally recognized testing laboratory to UL/CSA 60950 3rd Edition (North America) and EN60950 (International
- 2. CB Certificate from an internationally recognized test house in accordance with EN 60950

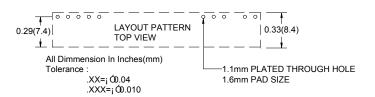
The S15-5S3.3 converters do not have an internal fuse. However, to achieve maximum safety and system protection, always use an input line fuse. The safety agencies require a time-delay fuse with a maximum rating of 20A.

7. Applications

7.1 Layout Design Challenges.

In optimizing thermal design the PCB is utilized as a heatsink. Also some heat is transferred from the SIP module to the main board through connecting pins. The system designer or the end user must ensure that other components and metal in the vicinity of the S15-5S3.3 meet the spacing requirements to which the system is approved.

Low resistance and low inductance PCB layout traces are the norm and should be used where possible. Due consideration must also be given to proper low impedance tracks between power module, input and output grounds.



VIEW IS FROM TOP SIDE Figure 4A. Recommended SIP Footprint

Recommended Pad Layout

Dimensions are in millimetes and(inches)

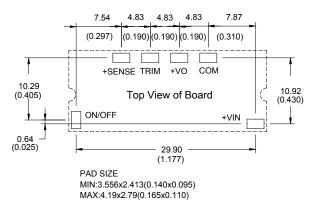


Figure 4B. Recommended SMT Footprint



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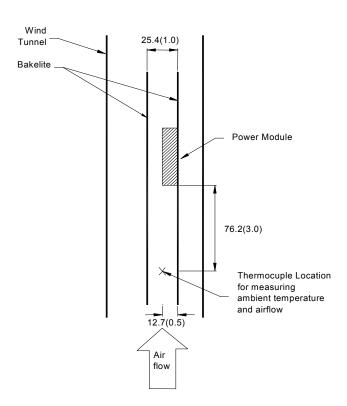
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7.2 Convection Requirements for Cooling

To predict the approximate cooling needed for the module, refer to the Power De-rating curves in Figures 9 and 10. These de-rating curves are approximations of the ambient temperatures and airflows required to keep the power module temperature below its maximum rating. Once the module is assembled in the actual system, the module's temperature should be checked as shown in Figure 5 to ensure it does not exceed 110°C.

Proper cooling can be verified by measuring the power module's temperature at Q1-pin 6 and Q2-pin 6 as shown in Figure 6A,6B.



Note: Dimensions are in millimeters and (inches)

Figure 5. Thermal Test Setup

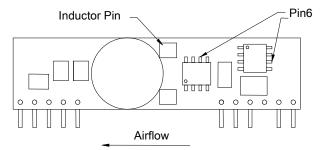


Figure 6A. Temperature Measurement Location for SIP

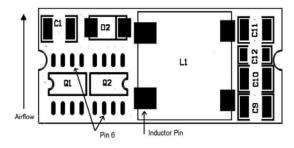


Figure 6B. Temperature Measurement Location for SMT

7.3 Thermal Considerations

The power module operates in a variety of thermal environments; however, sufficient cooling should be provided to help ensure reliable operation of the unit. Heat is removed by conduction, convection, and radiation to the surrounding environment. The thermal data presented is based on measurements taken in a set-up as shown in Figure 5. Figures 7, 8 represent the test data.

Note that the airflow is parallel to the long axis of the module as shown in Figure 6A for the SIP15.

The temperature at either location should not exceed 110 °C. The output power of the module should not exceed the rated power for the module (VO, set x IO, max).

The SMT15 thermal data presented is based on measurements taken in a wind tunnel. The test setup shown in Figure 5 and EUT need to solder on 33mm x 40.38mm(1.300" x 1.59") test pcb. Note that airflow is parallel to the long axis of the module as shown in Fig 6B



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7.4 Power De-Rating Curves

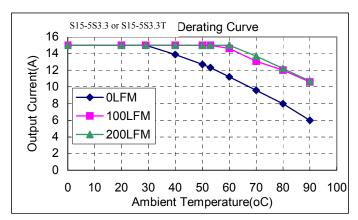


Figure 7. Typical Power De-rating for 5.0V IN(SIP15)

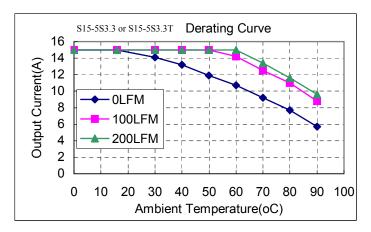


Figure 8. Typical Power De-rating for 5.0V IN (S15-5S3.3)

7.5 Input Capacitance at the Power Module

The SIP/SMT converters must be connected to a low AC source impedance. To avoid problems with loop stability source inductance should be low. Also, the input capacitors should be placed close to the converter input pins to de-couple distribution inductance. However, the external input capacitors are chosen for suitable ripple handling capability. Low ESR polymers are a good choice. They have high capacitance, high ripple rating and low ESR (typical <20m Ω). Electrolytic capacitors should be avoided. Circuit as shown in Figure 9 represents typical measurement methods for ripple current. Input reflected-ripple current is measured with a simulated source Inductance of 1uH. Current is measured at the input of the module.

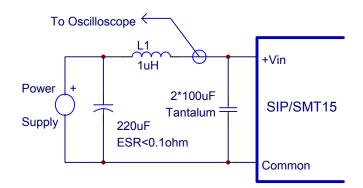


Figure 9. Input Reflected-Ripple Test Setup

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7.6 Test Set-Up

The basic test set-up to measure parameters such as efficiency and load regulation is shown in Figure 10. Things to note are that this converter is non-isolated, as such the input and output share a common ground. These grounds should be connected together via low impedance ground plane in the application circuit. When testing a converter on a bench set-up, ensure that -Vin and -Vo are connected together via a low impedance short to ensure proper efficiency and load regulation measurements are being made. When testing the Intronics' S15-5S3.3 under any transient conditions please ensure that the transient response of the source is sufficient to power the equipment under test. We can calculate the

- Efficiency
- Load regulation and line regulation.

The value of efficiency is defined as:

$$\eta = \frac{Vo \times Io}{Vin \times Iin} \times 100\%$$

Where: Vo is output voltage,

lo is output current,

Vin is input voltage,

lin is input current.

The value of load regulation is defined as:

$$Load.reg = \frac{V_{FL} - V_{NL}}{V_{NL}} \times 100\%$$

Where: V_{FL} is the output voltage at full load

V_{NL} is the output voltage at no load

The value of line regulation is defined as:

$$Line.reg = \frac{V_{HL} - V_{LL}}{V_{LL}} \times 100\%$$

Where: V_{HL} is the output voltage of maximum input voltage at full load. V_{LL} is the output voltage of minimum input voltage at full load.

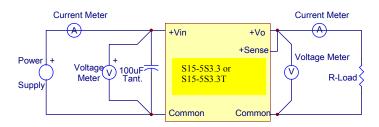


Figure 10. S15-5S3.3 Test Setup

7.7 Remote Sense Compensation

Remote Sense regulates the output voltage at the point of load. It minimizes the effects of distribution losses such as drops across the connecting pin and PCB tracks (see Figure 11). Please note however, the maximum drop from the output pin to the point of load should not exceed 500mV for remote compensation to work.

The amount of power delivered by the module is defined as the output voltage multiplied by the output current (VO x IO).

When using TRIM UP, the output voltage of the module will increase which, if the same output current is maintained, increases the power output by the module. Make sure that the maximum output power of the module remains at or below the maximum rated power.

When the Remote Sense feature is not being used, leave sense pin disconnected.

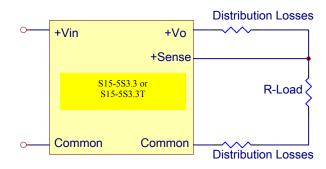


Figure 11. Circuit Configuration for Remote Sense Operation

7.8 S15-5S3.3 Output Voltage Adustment.

The output Voltage of the S15-5S3.3 can be adjusted in the range 0.9V to 3.63V by connecting a single resistor on the motherboard (shown as Rtrim) in Figure 12. When Trim resistor is not connected the output voltage defaults to 0.75V

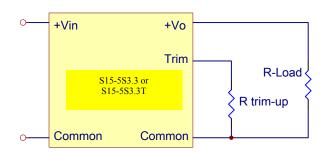


Figure 12. Trim-up Voltage Setup



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The value of Rtrim-up defined as:

$$Rtrim = \left(\frac{21070}{Vo - 0.75} - 5110\right) k\Omega$$

Where: Rtrim-up is the external resistor in $K\Omega$, Vo is the desired output voltage

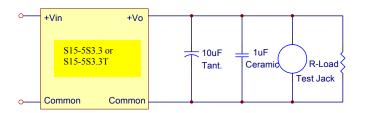
To give an example of the above calculation, to set a voltage of 3.3Vdc, Rtrim is given by:

Rtrim=
$$\left(\frac{21070}{3.3 - 0.75} - 5110\right)$$

Rtrin= $3.15 \text{ k}\Omega$

For various output values various resistors are calculated and provided in Table 2 for convenience.

Vo,set (V)	Rtrim (KΩ)
0.90	135.36
1.00	79.17



1.20	41.71
1.50	22.98
1.80	14.96
2.00	11.75
2.50	6.93
3.30	3.15
3.63	2.20

Table 2 - Trim Resistor Values

7.9 Output Ripple and Noise Measurement

The test set-up for noise and ripple measurements is shown in Figure 13. a 50Ω . coaxial cable with a 50Ω termination was used to prevent impedance mismatch reflections disturbing the noise readings at higher frequencies.

Figure 13. Output Voltage Ripple and Noise Measurement Set-Up

7.10 Output Capacitance

Intronics' S15-5S3.3 converters provide unconditional stability with or without external capacitors. For good transient response low ESR output capacitors should be located close to the point of load. For high current applications point has already been made in layout considerations for low resistance and low inductance tracks.

Output capacitors with its associated ESR values have an impact on loop stability and bandwidth. Intronics' converters are designed to work with load capacitance up-to 10,000uF. It is recommended that any additional capacitance, typically 1,000uF and low ESR (<20m(), be connected close to the point of load and outside the remote compensation point.

7.11 SMT Reflow Profile

An example of the SMT reflow profile is given in Figure 14.

Equipment used: SMD HOT AIR REFLOW HD-350SAR Alloy: AMQ-M293TA or NC-SMQ92 IND-82088 SN63

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Figure 14 – SMT Reflow Profile



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8. Mechanical Outline Diagrams

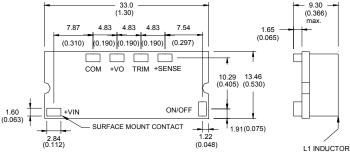
8.1 S15-5S3.3 or S15-5S3.3T Mechanical Outline Diagrams

Dimensions are in millimeters and (inches)

Tolerance : x.xx ± 0.02 in.(0.5mm) , x.xxx ± 0.010 in. (0.25 mm) unless otherwise noted

Figure 15. S15-5S3.3T Mechanical Outline Diagram

BOTTOM VIEW OF BOARD



Dimensions are in millimeters(Inches)

 $\label{eq:tolerances} \mbox{Tolerances}: X.X_{\dot{1}} \ \ \dot{\mbox{00.5mm}} (0.02\mbox{in}), X.XX_{\dot{1}} \ \ \dot{\mbox{00.25mm}} (0.010\mbox{in}), \mbox{unless otherwise noted}.$

Figure 16. S15-5S3.3 Mechanical Outline Diagram

8.2 SMT Tape and Reel Dimensions

The Tape Reel dimensions for the SMT module is shown in Figure 17.

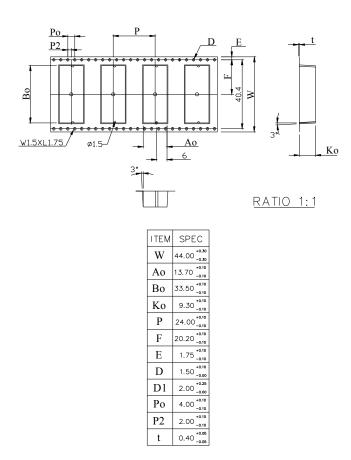


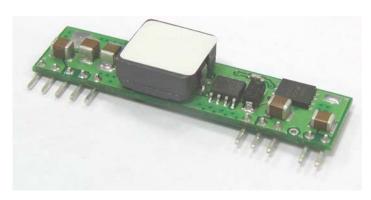
Figure 17 – SMT Tape and Reel Dimensions



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- **Applications**
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NON-ISOLATED DC-DC Converter S16-12S5T, S16-12S5 9.0-14Vin, 0.75-5.0Vout, 16A **APPLICATION NOTES** Ver. 10



S16-12S5T



S16-12S5



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Content

1. INTRODUCTION 2. MODELS	3 3	
3. 16A SIP/SMT CONVERTER FEATURES	3	
4. GENERAL DESCRIPTION	3	
4.1 Electrical Description	3	
4.2 Thermal Packaging and Physical Design.	4	
5. MAIN FEATURES AND FUNCTIONS	4	
5.1 Operating Temperature Range	4	
5.2 Over-Temperature Protection (OTP)	4	
5.3 Output Voltage Adjustment	4	
5.4 Safe Operating Area (SOA)	4	
5.5 Over Current Protection	4	
5.6 Remote ON/OFF	4	
5.7 UVLO (Under-Voltage Lockout)	5	
6. SAFETY	5	
6.1 Input Fusing and Safety Considerations.	5	
7. APPLICATIONS	5	
7.1 Layout Design Challenges.	5	
7.2 Convection Requirements for Cooling	5	
7.3 Thermal Considerations	6	
7.4 Power De-Rating Curves	7	
7.5 Efficiency vs Load Curves	10	
7.6 Input Capacitance at the Power Module	13	
7.7 Test Set-Up	13	
7.8 S16 Series Output Voltage Adustment.	14	
7.9 Output Ripple and Noise Measurement	14	
7.10 Output Capacitance	14	
7.11 SMT Reflow Profile	14	
8. MECHANICAL OUTLINE DIAGRAMS	15	
8.1 SIP/SMT16 Mechanical Outline Diagrams	15	
8.2 SMT Tape and Reel Dimensions	15	



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3. 16A SIP/SMT Converter Features

- High efficiency topology, typically 94% at 5.0Vdc
- Industry standard footprint
- Wide ambient temperature range, -40C to +85C
- Cost efficient open frame design
- Programmable output voltage via external resistor from 0.75 to 5.0Vdc
- No minimum load requirement (Stable at all loads)
- Remote ON/OFF
- Remote sense compensation
- Fixed switching frequency
- Continuous short-circuit protection and over current protection
- Over-temperature protection (OTP)
- Monotonic Startup with pre-bias at the output.
- UL/IEC/EN60950 Certified.

4. General Description

4.1 Electrical Description

A block diagram of the S16 Series converter is shown in Figure 1. Extremely high efficiency power conversion is achieved through the use of synchronous rectification and drive techniques. Essentially, the powerful S16 Series topology is based on a non-isolated synchronous buck converter. The control loop is optimized for unconditional stability, fast transient response and a very tight line and load regulation. In a typical pre-bias application the S16 Series converters do not draw any reverse current at start-up. The output voltage can be adjusted from 0.75 to 5.0vdc, using the TRIM pin with a external resistor. The converter can be shut down via a remote ON/OFF input that is referenced to ground. This input is compatible with popular logic devices; a 'positive' logic input is supplied as standard. Positive logic implies that the converter is enabled if the remote ON/OFF input is high (or floating), and disabled if it is low. The converter is also protected against over-temperature conditions. If the converter is overloaded or the ambient temperature gets too high, the converter will shut down to protect the unit.

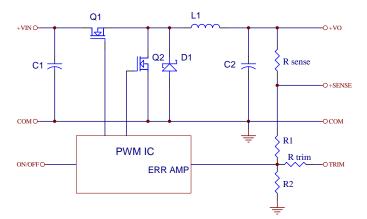


Figure 1. Electrical Block Diagram

1. Introduction

This application note describes the features and functions of Intronics' S16 Series of Non Isolated DC-DC Converters. These are highly efficient, reliable and compact, high power density, single output DC/DC converters. These "Point of Load" modules serve the needs specifically of the fixed and mobile telecommunications and computing market, employing economical distributed Power Architectures. The S16 Series provide precisely regulated output voltage range from 0.75V to 5.0Vdc over a wide range of input voltage (Vi=9.0 -14Vdc) and can operate over an ambient temperature range of -40°C to +85°C. Ultra-high efficiency operation is achieved through the use of synchronous rectification and drive control techniques.

The modules are fully protected against short circuit and over-temperature conditions. Intronics' world class automated manufacturing methods, together with an extensive testing and qualification program ensure that all S16 Series converters are extremely

2. Models

The adjustable S16 Series models are shown in table1.

Model	Input Voltage	Output Voltage	Output Current
S16-12S5T	9.0 – 14VDC	0.75 – 5.0VDC	16A
S16-12S5	9.0 – 14VDC	0.75 - 5.0VDC	16A

Table 1 - S16 Series Models

The S16 efficiency and input current at 12Vin are shown in table2.

Output	Output	t Input Current (mA)		F. (6) - 1 1
Voltage	Current	No Load	Full Load	Efficiency typ.
0.75V	16A	40	1299mA	77%
1.2V	16A	50	1928mA	83%
1.5V	16A	50	2326mA	86%
1.8V	16A	60	2727mA	88%
2.0V	16A	60	2996mA	89%
2.5V	16A	65	3704mA	90%
3.3V	16A	75	4783mA	92%
5.0V	16A	75	7092mA	94%

Table 2 - S16 Efficiency and Input Current



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Applications

Semiconductor Test Equipment

- Servers, Switches and Data Storage · Networking Gear
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4.2 Thermal Packaging and Physical Design.

The S16 Series uses a multi-layer FR4 PCB construction. All surface mount power components are placed on one side of the PCB, and all low-power control components are placed on the other side. Thus, the Heat dissipation of the power components is optimized, ensuring that control components are not thermally stressed. The converter is an open-frame product and has no case or case pin. The open-frame design has several advantages over encapsulated closed devices. Among these advantages are:

- Efficient Thermal Management: the heat is removed from the heat generating components without heating more sensitive, small signal control components.
- Environmental: Lead free open-frame converters are more easily re-cycled.
- Cost Efficient: No encapsulation. Cost efficient open-frame construction.
- Reliable: Efficient cooling provided by open frame construction offers high reliability and easy diagnostics.

5. Main Features and Functions

5.1 Operating Temperature Range

Intronics' S16 Series converters highly efficient converter design has resulted in its ability to operate over a wide ambient temperature environment (-40°C to 85°C). Due consideration must be given to the de-rating curves when ascertaining maximum power that can be drawn from the converter. The maximum power drawn is influenced by a number of factors, such as:

- Input voltage range.
- Output load current.
- Air velocity (forced or natural convection)
- Mounting orientation of converter PCB with respect to the Airflow.
- Motherboard PCB design, especially ground and power planes. These can be effective heat sinks for the converter.

5.2 Over-Temperature Protection (OTP)

The S16 Series converters are equipped with non-latching over-temperature protection. A temperature sensor monitors the temperature of the hot spot (typically, top switch). If the temperature exceeds a threshold of 130°C (typical) the converter will shut down, disabling the output. When the temperature has decreased the converter will automatically restart. The over-temperature condition can be induced by a variety of reasons such as external overload condition or a system fan failure.

5.3 Output Voltage Adjustment

Section 7.8 describes in detail as to how to trim the output voltage with respect to its set point. The output voltage on all models is trimmable in the range 0.75 – 5.0Vdc.

5.4 Safe Operating Area (SOA)

Figure 2 provides a graphical representation of the Safe Operating Area (SOA) of the converter. This representation assumes ambient operating conditions such as airflow are met as per thermal guidelines provided in Sections 7.2 and 7.3.

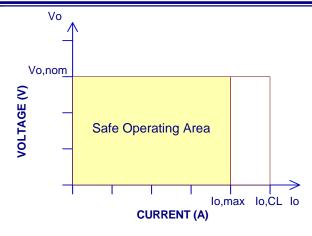


Figure 2. Maximum Output Current Safe Operating Area

5.5 Over Current Protection

All different voltage models have a full continuous short-circuit protection. The unit will auto recover once the short circuit is removed. To provide protection in a fault condition, the unit is equipped with internal over-current protection. The unit operates normally once the fault condition is removed. The power module will supply up to 150% of rated current. In the event of an over current converter will go into a hiccup mode protection.

5.6 Remote ON/OFF

The remote ON/OFF input feature of the converter allows external circuitry to turn the converter ON or OFF. Active-high remote ON/OFF is available as standard. The S16 are turned on if the remote ON/OFF pin is high(=Vin), or left open. Setting the pin low(<0.4Vdc) will turn the converter 'Off'. The signal level of the remote on/off input is defined with respect to ground. If not using the remote on/off pin, leave the pin open (module will be on). The part number suffix "N" is Negative remote ON/OFF version. The unit is guaranteed OFF over the full temperature range if this voltage level exceeds 2.8Vdc. The converters are turned on If the on/off pin input is low (<0.4Vdc) or left open. The recommended SIP/SMT remote on/off drive circuit as shown as figure 3, 4

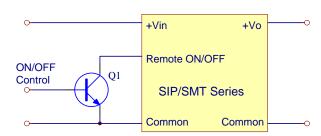


Figure 3. Positive Remote ON/OFF Input Drive Circuit

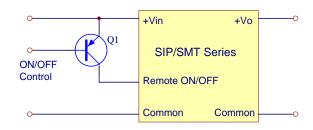


Figure 4. Negative Remote ON/OFF Input Drive Circuit



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Applications

• Distributed Power Architecture

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Recommended Pad Lavout

Dimensions are in millimetes and(inches)

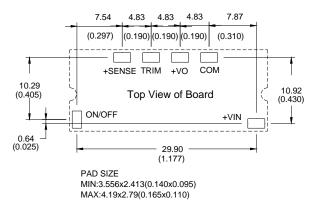
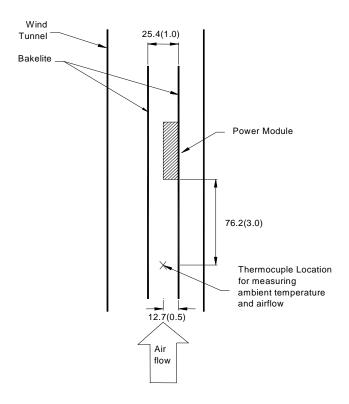


Figure 6. Recommended SMT Footprint

7.2 Convection Requirements for Cooling

To predict the approximate cooling needed for the module, refer to the Power De-rating curves in Figures 10 to 13. These de-rating curves are approximations of the ambient temperatures and airflows required to keep the power module temperature below its maximum rating. Once the module is assembled in the actual system, the module's temperature should be checked as shown in Figure 7 to ensure it does not exceed 120°C. Proper cooling can be verified by measuring the power module's temperature at Q1-pin 6 as shown in Figure 8,9.



Note: Dimensions are in millimeters and (inches)

Figure 7. Thermal Test Setup

5.7 UVLO (Under-Voltage Lockout)

The voltage on the Vcc pin determines the start of the operation of the Converter. When the input Vcc rises and exceeds about 8.0V the converter initiates a soft start. The UVLO function in the converter has a hysteresis (about 300mV) built in to provide noise immunity at start-up.

6. Safety

6.1 Input Fusing and Safety Considerations.

Agency Approvals: The power Supply shall be submitted to and receive formal approval from the following test agencies.

- 1. The power supply shall be approved by a nationally recognized testing laboratory to UL/CSA 60950 3rd Edition (North America) and EN60950 (International)
- 2. CB Certificate from an internationally recognized test house in accordance with EN 60950.

The S16 Series converters do not have an internal fuse. However, to achieve maximum safety and system protection, always

use an input line fuse. The safety agencies require a time-delay fuse with a maximum rating of 20A.

7. Applications

7.1 Layout Design Challenges.

In optimizing thermal design the PCB is utilized as a heat sink. Also some heat is transferred from the SIP/SMT module to the main board through connecting pins. The system designer or the end user must ensure that other components and metal in the vicinity of the

S16 Series meet the spacing requirements to which the system is approved.

Low resistance and low inductance PCB layout traces are the norm and should be used where possible. Due consideration must also be given to proper low impedance tracks between power module, input and output grounds. The recommended SIP/SMT footprint as shown as figure 5, 6.

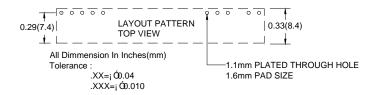


Figure 5. Recommended SIP Footprint



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- Data Communications Distributed Power Architecture
 - Telecommunications
 - Industrial / Medical

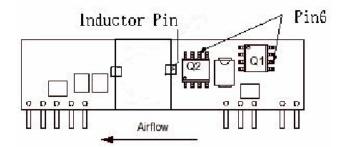


Figure 8. Temperature Measurement Location for SIP

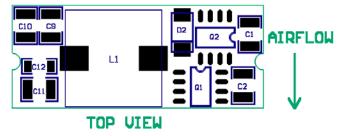


Figure 9. Temperature Measurement Location for SMT

7.3 Thermal Considerations

The power module operates in a variety of thermal environments; however, sufficient cooling should be provided to help ensure reliable operation of the unit. Heat is removed by conduction, convection, and radiation to the surrounding environment. The thermal data presented is based on measurements taken in a set-up as shown in Figure 7. Figures 10 to 13 represent the test data. Note that the airflow is parallel to the long axis of the module as shown in Figure7 for the SIP/SMT.

The temperature at either location should not exceed 120 °C. The output power of the module should not exceed the rated power for the module (VO, set x IO, max). The SMT05 thermal data presented is based on measurements taken in a wind tunnel. The test setup shown in Figure 7 and EUT need to solder on 33mm x 40.38mm(1.300" x 1.59") test pcb. Note that airflow is parallel to the long axis of the module as shown in Fig7.



S16 SERIES SIP or SMT **Version Application Notes**

Applications

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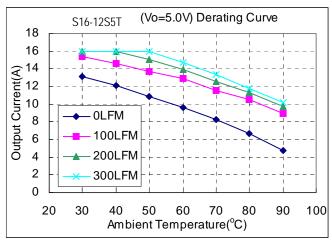
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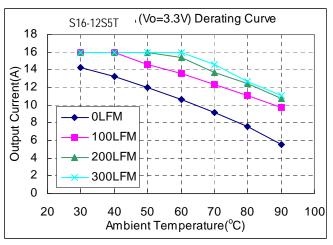
Data Communications

Telecommunications

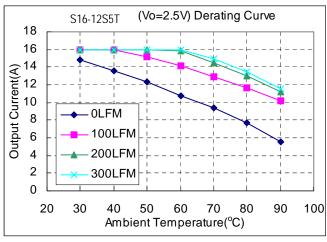
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7.4 Power De-Rating Curves









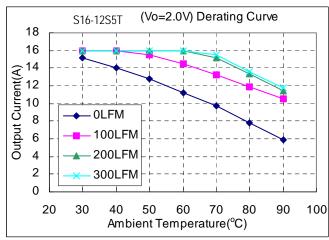
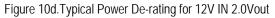
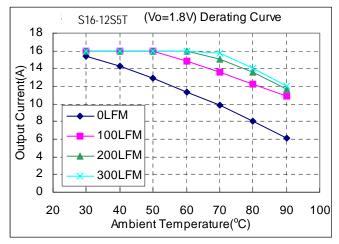


Figure 10c. Typical Power De-rating for 12V IN 2.5Vout





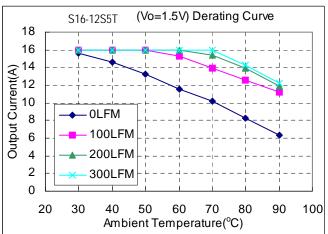


Figure 10e. Typical Power De-rating for 12V IN 1.8Vout Figure 10f. Typical Power De-rating for 12V IN 1.5Vout



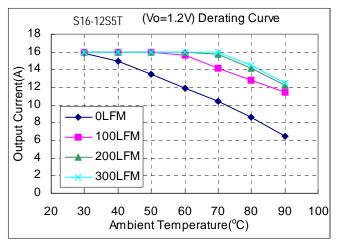
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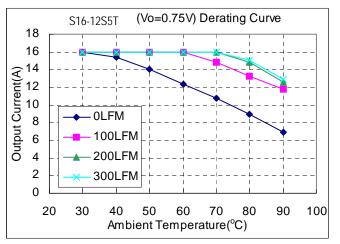
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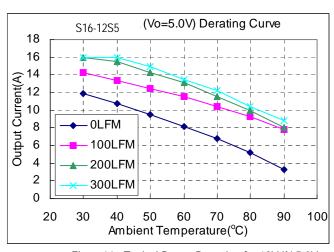




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Figure 10g. Typical Power De-rating for 12V IN 1.2Vout Figure 10h. Typical Power De-rating for 12V IN 0.75Vout



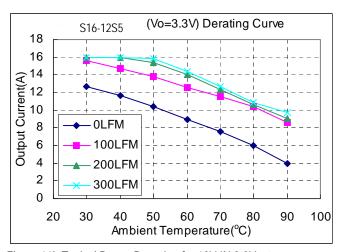
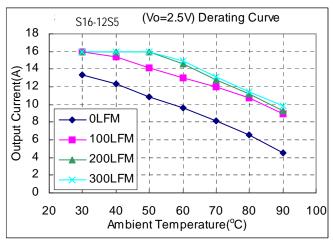


Figure11a.Typical Power De-rating for 12V IN 5.0Vout Figure 11b.Typical Power De-rating for 12V IN 3.3Vout



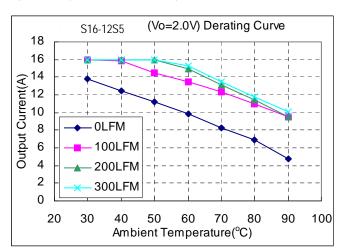


Figure 11c. Typical Power De-rating for 12V IN 2.5Vout Figure 11d. Typical Power De-rating for 12V IN 2.0Vout



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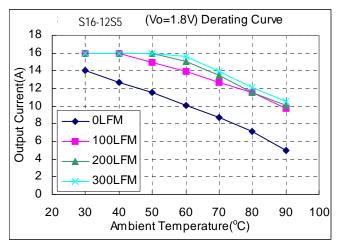
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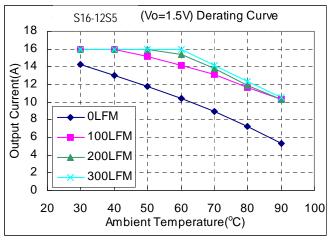
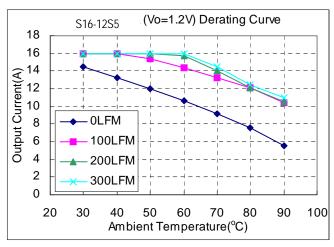


Figure 11e. Typical Power De-rating for 12V IN 1.8Vout

Figure 11d. Typical Power De-rating for 12V IN 1.5Vout



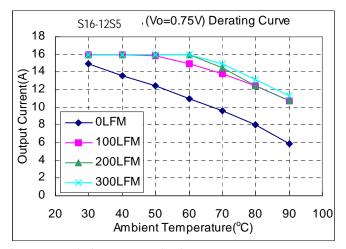


Figure 11f. Typical Power De-rating for 12V IN 1.2Vout Figure 11g. Typical Power De-rating for 12V IN 0.75Vout



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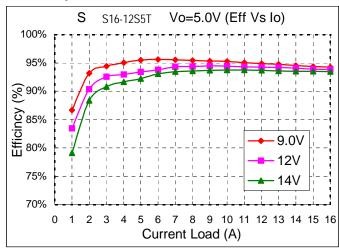
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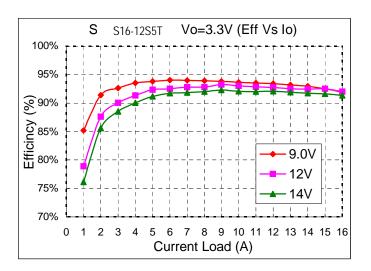
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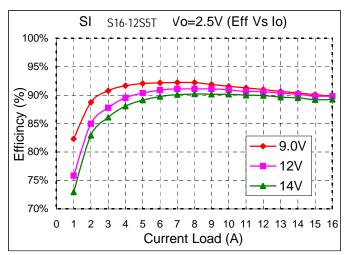
Telecommunications

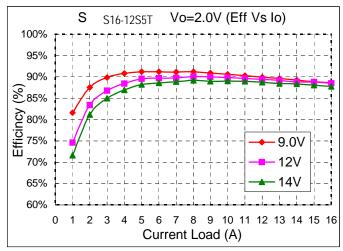
Industrial / Medical

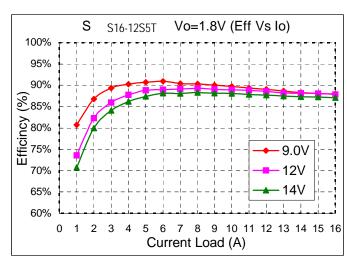
7.5 Efficiency vs Load Curves

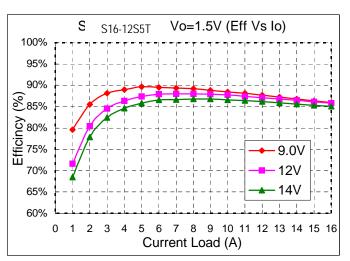












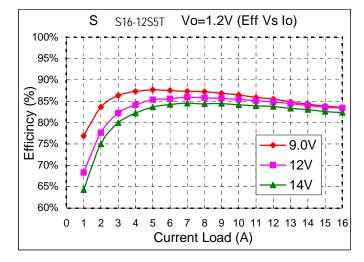


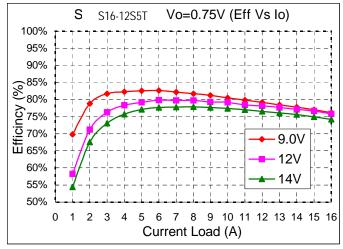
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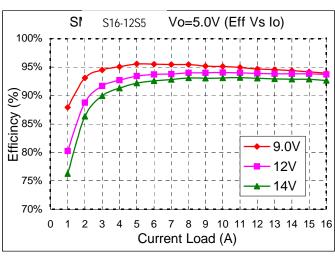
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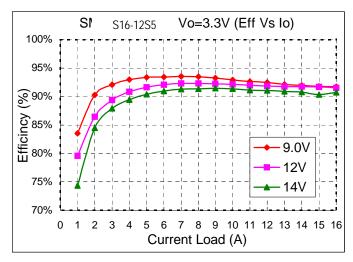
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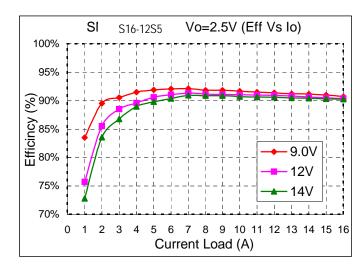
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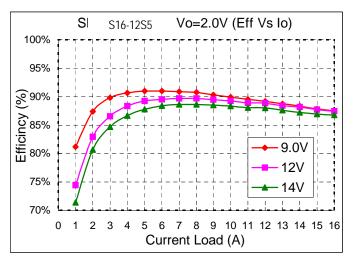












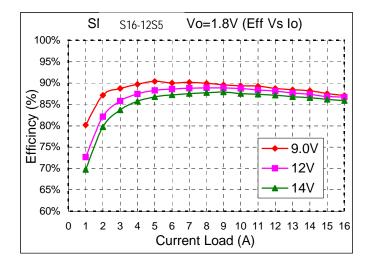


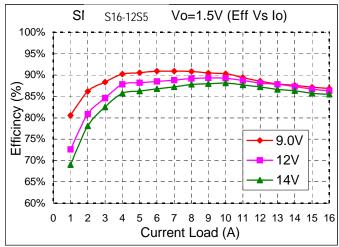
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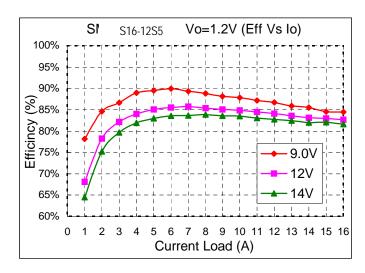
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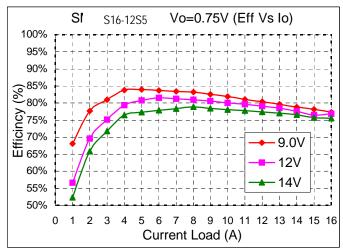
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7.6 Input Capacitance at the Power Module

The SIP/SMT converters must be connected to a low AC source impedance. To avoid problems with loop stability source inductance should be low. Also, the input capacitors should be placed close to the converter input pins to de-couple distribution inductance. However, the external input capacitors are chosen for suitable ripple handling capability. Low ESR polymers are a good choice. They have high capacitance, high ripple rating and low ESR (typical <100mohm). Electrolytic capacitors should be avoided. Circuit as shown in Figure 14 represents typical measurement methods for ripple current. Input reflected-ripple current is measured with a simulated source Inductance of 1uH. Current is measured at the input of the module

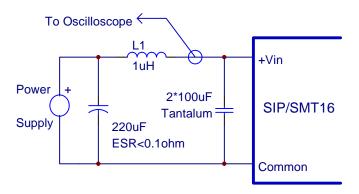


Figure 14. Input Reflected-Ripple Test Setup

7.7 Test Set-Up

The basic test set-up to measure parameters such as efficiency and load regulation is shown in Figure 15. Things to note are that this converter is non-isolated, as such the input and output share a common ground. These grounds should be connected together via low impedance ground plane in the application circuit. When testing a converter on a bench set-up, ensure that -V_{in} and -V_o are connected together via a low impedance short to ensure proper efficiency and load regulation measurements are being made. When testing the Intronics' S16 Series under any transient conditions please ensure that the transient response of the source is sufficient to power the equipment under test. We can calculate the

- Load regulation and line regulation.

The value of efficiency is defined as:

$$\eta = \frac{Vo \times Io}{Vin \times Iin} \times 100\%$$

Where: Vo is output voltage.

> lo is output current, Vin is input voltage,

lin is input current.

The value of load regulation is defined as:

$$Load.reg = \frac{V_{FL} - V_{NL}}{V_{NL}} \times 100\%$$

Where: V_{FL} is the output voltage at full load

 V_{NL} is the output voltage at no load

The value of line regulation is defined as:

$$Line.reg = \frac{V_{HL} - V_{LL}}{V_{LL}} \times 100\%$$

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 V_{HL} is the output voltage of maximum input voltage at full load. V_{LL} is the output voltage of minimum input voltage at full load.

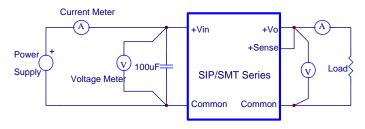


Figure 15. SIP/SMT16 Series Test Setup



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7.8 S16 Series Output Voltage Adustment.

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The output Voltage of the S16 can be adjusted in the range 0.75V to 5.0V by connecting a single resistor on the motherboard (shown as Rtrim) in Figure 16. When Trim resistor is not connected the output voltage defaults to 0.75V

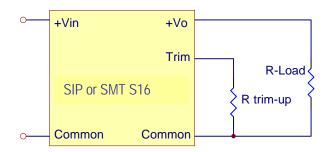


Figure 16. Trim-up Voltage Setup

The value of Rtrim-up defined as:

$$Rtrim = (\frac{10500}{Vo - 0.75} - 1000)$$

Where: Rtrim-up is the external resistor in ohm,

Vo is the desired output voltage

To give an example of the above calculation, to set a voltage of 3.3Vdc, Rtrim is given by:

$$Rtrim = (\frac{10500}{3.3 - 0.75} - 1000)$$

Rtrim = 3117 ohm

For various output values various resistors are calculated and provided in Table 3 for convenience.

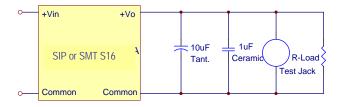
Vo,set (V)	Rtrim (Kohm)
0.75	Open
1.20	22.33
1.50	13.0
1.80	9.0
2.00	7.4
2.50	5.0
3.30	3.12
5.0	1.47

Table 3 - Trim Resistor Values

7.9 Output Ripple and Noise Measurement

The test set-up for noise and ripple measurements is shown in Figure 17. a coaxial cable with a 50ohm termination was used to prevent impedance mismatch reflections

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disturbing the noise readings at higher frequencies.

Figure 17. Output Voltage Ripple and Noise Measurement Set-Up

7.10 Output Capacitance

Intronics' S16 Series converters provide unconditional stability with or without external capacitors. For good transient response low ESR output capacitors should be located close to the point of load.

For high current applications point has already been made in layout considerations for low resistance and low inductance tracks.

Output capacitors with its associated ESR values have an impact on loop stability and bandwidth. Intronics' converters are designed to work with load capacitance up-to 8,000uF. It is recommended that any additional capacitance, Maximum 8,000uF and low ESR, be connected close to the point of load and outside the remote compensation point.

7.11 SMT Reflow Profile

An example of the SMT reflow profile is given in Figure 18. Equipment used: SMD HOT AIR REFLOW HD-350SAR Alloy: AMQ-M293TA or NC-SMQ92 IND-82088 SN63

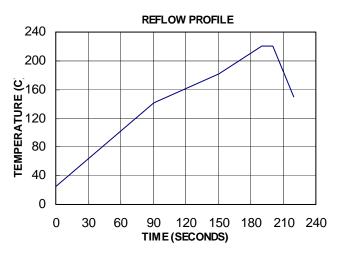


Figure 18 SMT Reflow Profile



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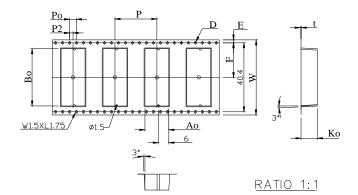
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8.2 SMT Tape and Reel Dimensions

The Tape Reel dimensions for the SMT module is shown in Figure 21.



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ITEM	SPEC
W	44.00 +0.30
Ao	13,70 +0.10
Во	33.50 +0.10
Ko	9.30 +0.10
P	24.00 +0.10
F	20.20 +0.10
Е	1.75 +0.10
D	1.50 +0.10
D1	2.00 +0.25
Po	4.00 +0.10
P2	2.00 +0.10
t	0.40 +0.05

Figure 21 – SMT Tape and Reel Dimensions

8. Mechanical Outline Diagrams

8.1 SIP/SMT16 Mechanical Outline Diagrams

Dimensions are in millimeters and inches

Tolerance: x.xx ±0.02 in. (0.5mm), x.xxx ±0.010 in. (0.25 mm) unless otherwise noted

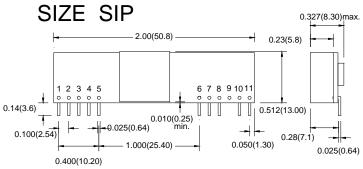
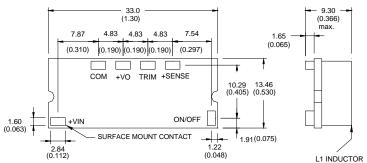


Figure 19 SIP16 Mechanical Outline Diagram

BOTTOM VIEW OF BOARD



Dimensions are in millimeters(Inches)

Tolerances :X.Xi \(\docume{0}\).5mm(0.02in),X.XXi \(\docume{0}\).25mm(0.010in),unless otherwise noted.

Figure 20 SMT16 Mechanical Outline Diagram